# WIRELESS INFRASTRUCTURE SOLUTIONS GUIDE

Digital Signal Processors, ASIC, Digital Upconverters/Downconverters, Data Converters, Amplifiers, Microcontrollers, Clock Distribution, Serial Gigabit, Interface, Logic, Power Management

40 2003



#### **TABLE OF CONTENTS**

#### **General Overview**

Tl's High-Performance, Flexible Solutions Enable Lowest Cost/Channel in Wireless Networks 3

#### **Signal Chain**

Signal Chain	
Complete Wireless Signal Chain Solutions	4
High-Performance DSPs Increase Base Station System Efficiency	5
High-Density Solutions for Voice-over-Packet and Data Transcoding	5
Comprehensive and Customizable UMTS Baseband Solution	6
ASIC Solutions Enable Next-Generation WI	8
Programmable Quad DDC or DUC for 3G Systems	9
Quad Digital Upconverter Provides Two 3G W-CDMA Channels	10
Quad Digital Downconverter Enables UMTS, Multi-Standard	10
Downconversion	10
14-Bit, 400-MSPS DAC with 2×/4× Interpolation	12
Dual DACS for I & Q Processing	12
Ultra-Low-Power 12-Bit, 40-MSPS Dual DAC	13
Low-Cost, Single DAC Family	13
0.6-GHz to 1-GHz Quadrature Modulators	14
Integer-N RF PLL Synthesizer	14
12-Bit ADC with Integrated DDC	15
Lowest-Power, Lowest-Cost ADC for BTS Receivers	15
50-MHz to 400-MHz Cascadeable IF Amplifiers	16
High-Speed, Fully Differential Op Amp	16
Fixed-Gain, High-Speed Op Amp with Power Down	17
Ultra-Low-Distortion, High-Speed Op Amps with Shutdown	17
2-GHz, Low Distortion, Current Feedback Amplifier	18
3–9-GHz GBW, Ultra-Low Noise, Voltage Feedback Op Amps	18
Ultra-Wide Band, Current Feedback Op Amp with Disable	19
Wideband, Ultra-Low-Noise, Voltage Feedback Amplifier	19
16-Bit RISC Flash MCU for only \$0.99	20
16-Bit RISC Flash MCU with Integrated 12-Bit ADC, Multiplier,	
and USARTs	20
Product Selection Guides	21
Timing and Interface Products	
Timing and Interface Overview	24
High-Speed, Point-to-Point 8-Channel Gigabit Ethernet Transceivers	25
Gigabit Ethernet- and Fibre Channel-Compliant Transceivers	25
LVDS SerDes Backplane Transmitter/Receiver Chipsets	26
16:1 Serializer/Deserializer Transceivers with PRBS Testability	26
3- or 4-Channel, Point-to-Point Transmitter and Receiver Pair	27
LVPECL/CML/LVDS Repeaters/Translators and Crosspoint Switches	27
Multipoint-LVDS for Backplanes and Cables	28
Low-Voltage Clock Drivers for Clock-Distribution Applications	28
Low-Jitter Clock Multiplier with Programmable Delay and	
Phase Alignment	29
3.3-V ×4 Clock Multiplier with 8 Outputs	29
Gunning Transceiver Logic Plus	30
Product Selection Guides	31
Logic	
16-Bit Buffer/Driver with 3-State Outputs	36
Low-Voltage Quadruple-FET Bus Switch	36
Product Selection Guides	37
	57
Power Management	
Power Management Overview	38
Point-of-Load Power Modules Offer Auto-Track™ Sequencing	39
75-W/100-W Converters Offer 90% Efficiency	39
Triple-Output Modules Feature 50% Smaller Footprint Plus	
Sequencing	40
-48 V, 8-Pin, Hot Swap Controllers	40
High-Efficiency Synchronous Buck DC/DC Controllers	41
Synchronous Buck DC/DC Converters with Integrated MOSFETS	41
Tracking Switcher with Integrated FETs for Sequencing	42
95% Efficient, 600-mA, Step-Down Converters	42
Dual, 4-Amp, MOSFET Gate Driver	43
LoadShare Controller for Parallel Power Supplies	43
Low-Input-Voltage, Output-Cap-Free 1-A LDOS	44
Ultra-Low-Noise, High PSRR, Fast-RF LDO in SOT-23	44
Product Selection Guides	45

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#### **Product Information Centers**

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France	0	+33 (0) 1 30 70 11 64
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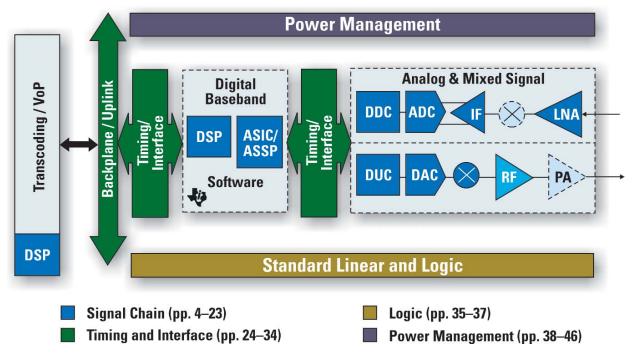
Printed in U.S.A. at Earth Color, Houston, Texas Cover photos used with permission from Ericsson.

#### **GENERAL OVERVIEW** TI'S HIGH-PERFORMANCE, FLEXIBLE SOLUTIONS ENABLE LOWEST COST/CHANNEL IN WIRELESS NETWORKS

Transitioning from the voice-centric services of a 2G network to the multimedia-dominated data of 2.5G and 3G presents designers of wireless infrastructure systems with a number of challenges, such as how to reduce cost per channel while effectively increasing capacity, processing higher data rates and supporting several multimedia standards simultaneously. At the same time though, designers must address the usual engineering questions of size, cost and power consumption.

Base station manufacturers need a broad portfolio of flexible products to provide a large degree of freedom when it comes to partitioning and migrating various critical tasks within systems as they evolve. Successful manufacturers will be able to efficiently customize their system offerings for each cellular technology and standard, thus enabling network evolution for service providers in a cost-effective manner.

TI's high-performance solutions enable more simultaneous voice and data calls so that **base station manufacturers** can support more user terminals including cell phones, smartphones, wireless PDAs, Internet appliances and other types of devices. This results in improved profitability for the service provider, which ensures customer satisfaction for the infrastructure system manufacturer. With higher capacity systems capable of higher data rates, service providers will be able to reduce subscriber churn and generate more revenue. In addition, TI's unmatched system expertise will help manufacturers lower development costs and rapidly deliver new 2.5G and 3G systems to market.



#### Generic Wireless Infrastructure System

#### **COMPLETE WIRELESS SIGNAL CHAIN SOLUTIONS**

In wireless infrastructure (WI) systems, designers must address several cross-disciplinary issues in the signal chain or that partition of the system where signals are processed. These challenging issues involve analog, mixed-signal, DSP, and chip-rate solutions, such as operational amplifiers (op amps). Highly flexible solutions provide system designers with the right level of hardware/software partitioning for cost-effective system-level products that can be brought to market quickly. In addition, highly flexible WI systems will better protect the manufacturer's investment in software.

For 3G base station architectures and Voice-over-Packet (VoP) applications, the combination of TI's high-performance TMS320C64x<sup>™</sup> DSP generation and its leading-edge ASIC capability provides customers with a winning wireless infrastructure solution. And, TI's unparalleled silicon expertise ensures that system designers receive state-of-the-art ASIC capability.

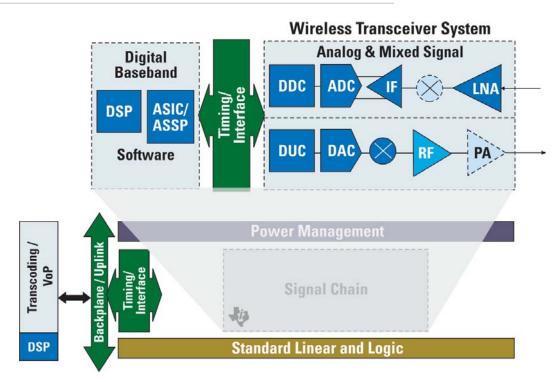
TI's digital upconverters (DUCs) and digital downconverters (DDCs) lead the industry in performance. These DDCs and DUCs can support multiple standards from 2G to 2.5G and 3G. With the recent introduction of the industry's best performing 14-bit 400-MSPS DAC, TI supports high-intermediate frequencies and 3G multi-carrier applications like the four-carrier W-CDMA.

Innovative architectures and technology have made TI's operational amplifiers some of the leading solutions in the industry. For example, the patented architecture of the THS4271 makes it the only op amp to achieve low noise, low distortion, and high slew rate with unity gain stability.

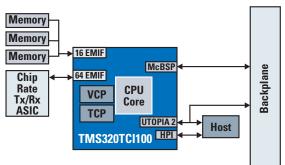
And the THS4302 leverages a new fully complimentary bipolar silicon-germanium fabrication process to deliver the first op amp with over 10 GHz of gain bandwidth. These devices and a wide selection of fully differential op amps give TI the most comprehensive array of high-speed, high-performance amplifiers for wireless infrastructure applications.

#### TO KNOW MORE >

For detailed information about sig chain ICs for wireless infrastructu	-
DSPs	5
Comprehensive UMTS baseband solution	6
ASIC	8
DUC/DDC	9
Up/Down converters	10
Data converters	11
Quadrature modulator	14
Synthesizers	14
Amplifiers	16
Microcontrollers	20
Product selection guides	21



TMS320TCI100 DSP in Symbol-Rate Processing for 2G, 2.5G, and 3G Applications



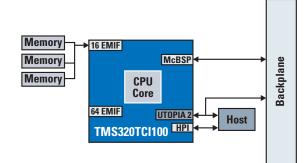
#### Applications:

- Symbol-rate processing for 2G, 2.5G, and 3G (shown above)
- Assist in chip-rate processing

DSP Block Diagram – TMS320TCI100 DSP

• Layer 2 processing in RNC

#### Timer 0 VCP Timer 1 TCF Timer 2 L1 Cache Direct Mapped, 16 KBytes Total EMIF 64 (64 Channel) **Total** EMIF 16 TMS3200 L2 Cache/Memory, 4 Banks, 1 MByte DMA Controller **Register File A Register File B** Enhanced L1 S1 M1 D1 D2 M2 S2 L2 PCI HPI 32 GPIOS 11D Cache 2-Way Set Associative 16 KBytes Total GPI016 Power Down Logic PLL



#### TMS320TCI100 DSP in a Voice Encode and Decode Application

#### Applications:

- Voice encode and decode (shown above)
- Network control processing
- Data formatting and routing

### HIGH-PERFORMANCE DSPs INCREASE BASE STATION SYSTEM EFFICIENCY

#### Get samples and application reports at: www.ti.com/sc/device/tms320tci100

#### Key Features:

- Industry-leading 90-nanometer process node
  - 720 MHz core performance
  - Power-efficient design (~600-mW core power)
  - High integration through state-of-the-art CMOS manufacturing process
- DSP designed for wireless infrastructure applications
  - Integrated Viterbi (VCP) and Turbo (TCP) coprocessors
  - TCP supports over 35 data (384 kbps) channels
  - VCP enables over 600 voice (7.95 kbps AMR) channels
- Complements TCI110 and TCI120 receive and transmit accelerators for wideband CDMA
- Rich mix of robust peripherals
- Two high-bandwidth (up to 10 Gbps), flexible interfaces to external memory
- Host port with glueless interface to most GPP
- UTOPIA II port for interface to communication network
- PCI for high-performance standard local bus
- Object-code compatible with all TMS320C6000™ DSPs
- Pin compatible with TMS3206415 and TMS320C6416 DSPs

#### HIGH-DENSITY SOLUTIONS FOR VOICE-OVER-PACKET (VoP) AND DATA TRANSCODING TMS320C55x™/TMS320C64x™ DSP Generations + Telogy

Software

Get samples and application reports at: www.ti.com/wisolutions\_vop

The TMS320TCI100 DSP also fits well in voice-transcoding, mobile switching-center, and media-gateway applications. Combining the optimized TCI100 solution with TI's high-density, field-hardened voice-over-packet (VoP) gateway solutions addresses the tough challenges facing service providers deploying packet-based networks.

#### Key Features:

- Flexible, carrier-grade solution
  - Field-proven Telogy software with over 50 million total ports shipped
- Carrier-certified echo cancellation
- Telogy software framework optimized for the TMS320C64x and TMS320C55x DSP generations
- Extensive voice CODEC suite
  - Includes wireless codecs such as SMV, EVRC, AMR, WB-AMR and QCELP

#### COMPREHENSIVE AND CUSTOMIZABLE UMTS BASEBAND SOLUTION UMTS Baseband Platform

TI's UMTS wireless infrastructure digital baseband platform is a comprehensive silicon and software product offering that enables the design of low-cost, high-density UMTS channel cards. The TCI1x platform supports the 3GPP FDD Release 99 standard as well as the HSDPA channels as per Release 5 of the 3GPP FDD standard. The platform consists of a high-performance wireless infrastructure tailored DSP and tightly coupled programmable accelerators. The design achieves a low cost-per-channel solution by leveraging an efficient pooling of silicon and memory resources on the chip-rate accelerators and optimally partitioning the symbol rate and chip rate functions between the DSP and accelerators.

The UMTS platform offering includes:

#### TMS320TCI100 DSP

- Industry leading 720 MHz core
- VCP and TCP coprocessors
- Pin and code compatible with TMS320C64x<sup>™</sup> DSPs

#### TMS320TCI110

- Single device for de-spreading, RACH and searching
- Configured and controlled via DSP
- The device is highly customizable with parameters such as number of users, number of fingers per user, correlation lengths and accumulation lengths configured via DSP software
- Efficient host interface between the TCI110 and the TCI100 DSP resulting in a high-channel-density solution

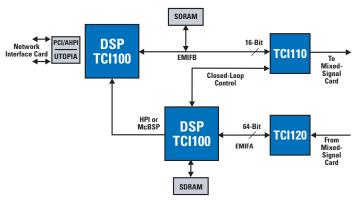
#### TMS320TCI120

- The TCI120 is a highly configurable downlink chip-rate accelerator
- Configured and controlled by the DSP
- The channel block is made up of 9 channel groups and supports a total of 288 downlink channel elements that can be configured as common or dedicated channels
- The TCI120 supports HSDPA as per Release 5 of the 3GPP standard
- Support for all the common channels, variable-rate dedicated channels, shared channels and compressed mode as per Release 99 of the 3GPP standard

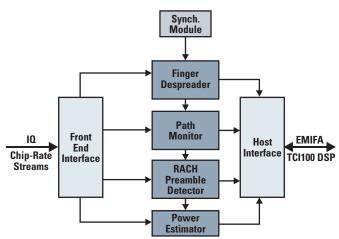
#### TCI1x Platform Software

- Physical layer reference design which includes layer 1 application and physical layer services manager
- The TCI1x hardware abstraction layer abstracts the hardware implementation details
- Highly optimized symbol- and chip-rate software modules
- TCI110 and TCI120 device control software

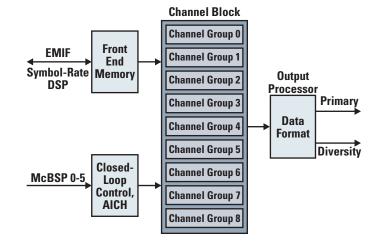
UMTS Platform-Based Channel Card



TCI110



TCI120



**Power Management** 

TCIStudio

Load Conligurati New	on ⊂ Saved ⊂ Conformance Test Co		Configuration Connect To Proxy	Wireless Channel.
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TCI1x Development and Evaluation Tools

- The familiar Code Composer Studio (CCStudio) suite of development tools including the debug, profiling, and tuning tools allows for faster software development
- TCIStudio suite of evaluation and analysis tools includes accelerator probes and performance analysis tools
- The TCIStudio along with the TCI1x Evaluation Module (EVM) help carry out the evaluation and performance analysis of the TCI1x accelerators and software
- The EVM also allows for initial code development before the customer's channel card is ready

#### Key Features:

- Customizable and flexible hardware configured and controlled through DSP software
- Comprehensive silicon and software UMTS baseband product offering
- TCl1x hardware abstraction layer provides a higher level of device abstraction to the user enabling them to develop a hardware independent application
- CCStudio, TCIStudio and EVM reduce the time-to-market by making software development quicker and easier

#### Applications:

• Low-cost, high-channel-density UMTS channel card

TImePilot

(TI + 3rd Party

Tools)

n

#### ASIC SOLUTIONS ENABLE NEXT-GENERATION WIRELESS INFRASTRUCTURE (WI) ASIC

#### For detailed information, visit:

#### www.ti.com/sc/asic

For further information, please contact your local TI Sales Representative (see page 2)

- Global leadership in semiconductor manufacturing
  - 0.18  $\mu m$  55 nm (Ldrawn) nodes. 95-nm (Ldrawn) Cu product 15% faster than competition
  - High-performance/density library, I/O, and memory for varying wireless infrastructure ASIC needs
  - Packaging: High-performance flip chip
- Experienced, flexible, and global design services
  - Worldwide design center staff for on-site support
  - Experienced WI applications team for system-level support
  - Collaborative design, traditional floor planning, place and route
  - Design kit with online documentation and full application notes
- System-level integration
  - Proven success on numerous multi-million gate designs
  - IP targeting WI, high-speed interfaces, and I/O (RapidIO / SerDes)
  - IP-Ethernet, DSP, microprocessor cores, broad array of peripherals
- Comprehensive ASIC cells and tool support
  - Robust module library/rich core library
  - Open EDA tool/flow support
  - Analog converter functions

#### Wireless Infrastructure Applications:

- Application-specific digital downconverter/digital upconverter
- Base-band processing
  - Chip-rate and symbol-rate processing for CDMA systems
  - Combining/decombining/bridge chips
- Specialized applications
  - Viterbi/turbo decoding
  - Switching matrix
- Network control and interface processing
  - Base station uplink
  - RNC control and protocol processor
- Transcoding/echo canceller
  - Customized applications
- Embedded SOC designs
  - High performance
  - Low peak power
- PA linearization



Support

Docs, Apps

Libraries

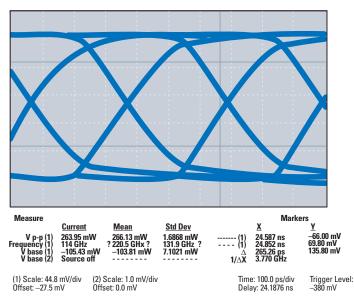
I/Os, Gates



High Performance SR40, SR50

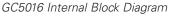
P&R

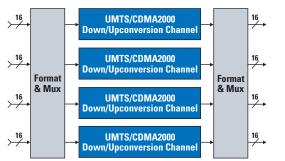
**3rd Party** 



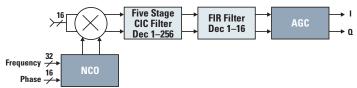
Leading-Edge IP: SoC with Multiple High-Performance SerDes Links at 3.2-Gbps

Logic

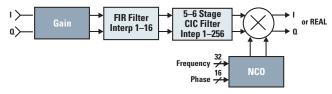




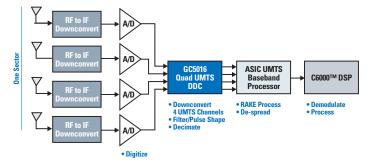
#### Downconversion Mode Channel Detail



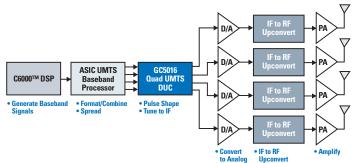
#### Upconversion Mode Channel Detail



#### GC5016 UMTS Four-Element Beamform Base Station Receiver



#### GC5016 UMTS Four-Element Beamform Base Station Transmitter



#### PROGRAMMABLE QUAD DDC OR DUC FOR 3G SYSTEMS GC5016



### Get samples, datasheets, application reports, and EVMs at: www.ti.com/sc/device/gc5016

Each one of the GC5016's four channels can be independently programmed to perform digital upconversion or downconversion of 3G systems such as W-CDMA or CDMA2000. Customers can choose to use the device as a programmable digital upconverter or downconverter. Alternatively, they can use the device to implement a two-channel upconversion and a two-channel downconversion simultaneously on a single chip.

As with its predecessors, the GC5016 continues to offer the best performance in the industry by delivering better than 115 dB of spurious-free dynamic range, exceeding industry requirements. While the maximum input data rate for each channel is the fastest in the industry (at 150 MSPS) by more than 35%, it can provide even faster input data rates of up to 300 MSPS by combining two channels for even wider bandwidth applications.

In the upconversion mode, the GC5016 accepts real or complex signals, interpolates them, and modulates them to selected intermediate frequencies that are then output to a digital-to-analog converter, such as the DAC904, DAC2904, or DAC5686. In the downconversion mode, the GC5016 accepts digital signals from an analog-to-digital converter, such as the ADS5410.

#### Key Features:

- Input clock rates
  - Up to 150 MSPS
  - Up to 300 MSPS in two-channel even/odd mode
- SFDR: 115 dB
- Integrated AGC
- FIR filter block consists of 16 cells providing up to 256 filter taps per channel
- 64 parallel input bits and 64 parallel output bits provide flexible I/O options
- Multiple multiplex output options
- Future-proof filter performance, clock rate, and bandwidth
- Power dissipation: 1 W at 100 MHz with all four channels in operation

#### Applications:

- Process four-channel UMTS in both downconvert or upconvert modes, as well as combination upconvert and downconvert mode
- Efficient and economic beamforming
- Low power is ideal for micro and pico base stations

Timing & Interface

Read more about Wireless Infrastructure solutions at www.ti.com/wisolutionsguide

#### QUAD DIGITAL UPCONVERTER PROVIDES TWO 3G W-CDMA CHANNELS GC4116

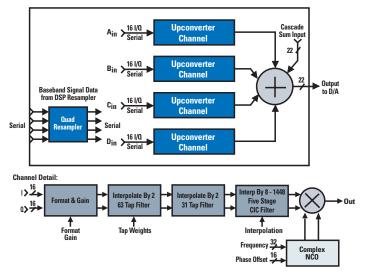
Get samples, datasheets, and IBIS models at: www.ti.com/sc/device/gc4116

The GC4116 is the first digital upconverter (DUC) to support multiple standards. The chip can upconvert four narrowband channels and up to two UMTS/CDMA2000-3x channels. The GC4116 also can directly accept QPSK, GMSK, or QAM symbols for transmit filtering or pulse shaping.

#### Key Features:

- Output rates up to 106 MSPS
- Four identical upconvert channels
- 16-bit real or complex inputs, with summed output
- Independent frequency, phase and gain controls
- Serial interface controller simplifies interfacing with ASICs or DSPs
- Low power: 117 mW (per GSM channel), up to 305 mW (per UMTS channel)

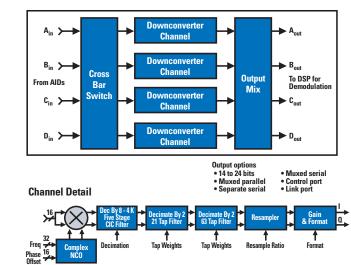
#### GC4116 DUC Block Diagram



#### Applications:

- Wireless base transceiver stations: macro, micro, and pico
- Repeaters
- Wireless local loop
- Cable headend and customer premise equipment

#### GC4016 DUC Block Diagram



#### Applications:

- Cellular base transceiver stations: macro, micro, and pico
- Repeaters
- Wireless local loop
- Cable headend and customer premise equipment

#### QUAD DIGITAL DOWNCONVERTER ENABLES UMTS, MULTI-STANDARD DOWNCONVERSION GC4016

Get samples, datasheets, and IBIS models at: www.ti.com/sc/device/gc4016

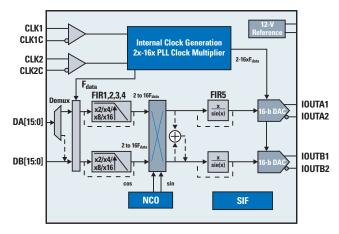
The GC4016 is the first digital downconverter (DDC) supporting multiple wireless standards, including 3G standards. The GC4016 can downconvert two UMTS/CDMA2000-3x with 2x oversampling or one channel with 4x oversampling.

#### Key Features:

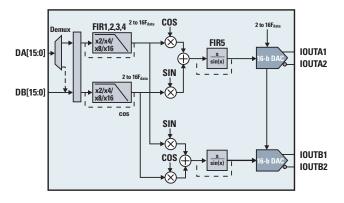
- Input rates up to 100 MSPS
- Four independent Digital Down Convert (DDC) channels
- Independent decimation and resampling, tuning, phase and gain controls
- Built-in diagnostics
- > -115 dBc spurious free dynamic range
- Low power: 115 mW (per GSM channel), up to 620 mW (per 3.84-MB UMTS channel)

Logic

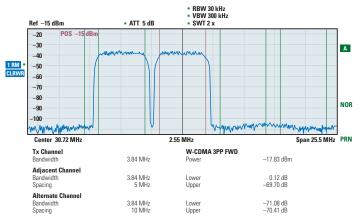
DAC5686 Internal Block Diagram



DAC5686 in Single Sideband Mode



#### DAC5686 Performance Plot



#### Applications:

- Cellular BTS
  - CDMA: W-CDMA, CDMA2000, IS-95
- TDMA: GSM, IS-136, EDGE/UWC-136
- Baseband I&Q transmit
- Low-data-rate interface for quadrature modulation
- Single sideband upconversion
- Diversity transmit

#### 16-BIT, 500-MSPS PROGRAMMABLE DUAL DAC DAC5686



#### www.ti.com/sc/device/dac5686

DAC5686 is designed to allow low data rate transfer from the ASIC to the DAC. The DAC5686's superior performance enables transmissions of up to four W-CDMA carriers at high intermediate frequencies. The DAC5686 can be used in three modes of operation.

#### A. Dual-Channel

The interpolation filters increase the DAC update rate, resulting in reduced sin x /x roll off. This greatly relaxes the requirements for analog-post filtering.

#### **B. Quadrature Modulation Mode**

This mode is used for baseband modulation or a two-channel digital IF system. While channel selection is done through complex mixing in the ASIC, the DAC5686 interpolates this incoming low-data-rate signal into higher-data rates. Then, on-chip mixing using a flexible 32-bit programmable NCO provides the final IF upconversion. Optional  $f_s/4$  mixing is available for lower power operation.

#### C. Single Sideband Upconversion Mode

This mode gives users the best interface to an analog upconverter, such as the TRF3701, for low-cost transmit solution. Complex mixing using the NCO can be used to offset the baseband signal from the LO frequency. The LO feed through an unwanted side band can then be attenuated by IF filtering at RF.

#### Key Features:

- 500-MSPS maximum DAC update rate
- 71 dBc SNR in 100-kHz BW for  $f_{OUT} \le 40$  MHz
- -82 dB IMD for four-tone CW input signal, each tone at -12 dBFS (f<sub>OUT</sub> = 15.6, 15.8, 16.2, 16.4 MHz)
- Low power dissipation: 440 mW (SSB mode)
- Selectable 2× to 16× interpolation, dual-channel
- On-chip 2x–16x PLL clock multiplier, PLL bypass mode
- Differential scalable current outputs: 2 mA to 20 mA
- 1.8-V digital / 3.3-V analog supply
- 1.8-V / 3.3-V CMOS-compatible interface
- Packaging: 100-HTQFP (PowerPAD™)

#### W-CDMA ACPR Performance:

- W-CDMA 1 carrier:
  - 74-dBc baseband, 245.76 MSPS
  - 77-dBc IF = 30.72 MHz, 245.76 MSPS
  - 71-dBc IF = 61.44 MHz, 245.76 MSPS
- W-CDMA 2 carrier:
  - 74-dBc IF = 30.72 MHz, 245.76 MSPS
  - 71-dBc IF = 61.44 MHz, 245.76 MSPS
  - 67-dBc IF = 122.88 MHz, 491.52 MSPS
- W-CDMA 4 carrier:
  - 67-dBc IF = 61.44 MHz, 245.76 MSPS
  - 64-dBc IF = 122.88 MHz, 491.52 MSPS



Logic

Read more about Wireless Infrastructure solutions at www.ti.com/wisolutionsguide

#### 14-BIT, 400-MSPS DAC WITH 2X/4X INTERPOLATION DAC5674

Get samples, datasheets, app reports and EVMs at: www.ti.com/sc/device/dac5674

The DAC5674 is a digital-to-analog converter integrated with a cascade of up to two 2× interpolation filters. The digital filtering option allows either a low pass or high pass mode which enables users to select the higher-order image for increased output frequency, potentially reducing an IF mixer stage. The low-pass interpolation mode provides excellent SFDR performance that enables multi-carrier architectures in the first Nyquist zone of up to 40-MHz IF with relaxed filter requirements.

#### Key Features:

- High W-CDMA ACPR:
  - 73 dB @ 15.36-MHz single carrier
  - 70 dB @ 46.08-MHz single carrier and 19.2-MHz dual carrier
- 2× or 4× interpolation with configurable low-pass/high-pass mode
- On-chip PLL with bypass option
- 1.8-V Digital and 3.3-V Analog supply operation
- 1.8-V/3.3-V CMOS-compatible interface
- Packaging: 48-lead PowerPAD™ HTQFP

# DUAL DACS FOR I & Q PROCESSING DAC2900, DAC2902, DAC2904

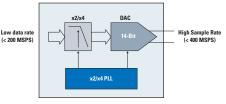
Get samples, datasheets, and EVMs at: www.ti.com/sc/device/partnumber Replace partnumber in URL with dac2900, dac2902, or dac2904

The two integrated DAC channels of the DAC290x family enable the I and Q channels to have close gain matching to maintain low error-vector magnitudes. These channels also provide high performance at low cost and low power. The 10-, 12-, and 14-bit family is pin compatible, allowing easy resolution upgrades.

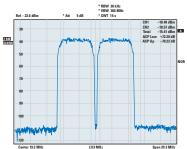
#### Key Features:

- High SFDR:
  - DAC2900: 68 dB at  $f_{OUT}$  = 20 MHz
  - DAC2902: 70 dB at  $f_{OUT}$  = 20 MHz
  - DAC2904: 78 dB at f<sub>OUT</sub> = 10 MHz
- Power: 310 mW
- Power-down mode: 23 mW
- Low glitch: 2 pVs
- Internal reference
- Packaging: 48-lead TQFP

#### DAC5674 Internal Block Diagram



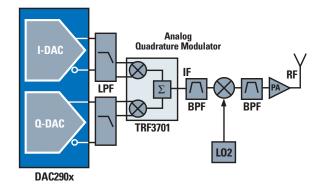
Dual-Carrier W-CDMA with ACPR of 70 dB @ 19.2 MHz



Applications:

- Cellular BTS:
  - CDMA: W-CDMA, CMDA2000, IS-95
- TDMA: GSM, IS-136, EDGE/UWC-136
- Low-data-rate interface
- Wireless local loop

DAC290x in Baseband Sampling Transmitter System

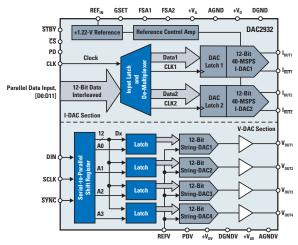


#### Applications:

- Base stations, WLL, WLAN
- Direct digital synthesis (DDS)
- Baseband sampling transmitter
- Diversity transmitter

Logic

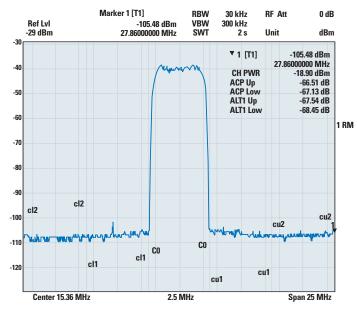
#### DAC2932 Functional Block Diagram



#### Applications:

- Transmit channels
  - I and Q
  - PC card modems: GPRS, CDMA
- Wireless network xards (NICs)
- Signal synthesis (DDS)
- Portable medical instrumentation
- Arbitrary waveform generation (AWG)

#### Single-Channel W-CDMA Signal on DAC904 with 15.36-MHz Input @ 122.88 MSPS



#### Applications:

- Transmit channel
  - Wireless base station
  - Wireless local loop
  - Digital microwave

# ULTRA-LOW-POWER 12-BIT, 40-MSPS DUAL DAC

#### DAC2932

Get samples, datasheets, app reports and EVMs at: www.ti.com/sc/device/dac2932

The DAC2932 is a 12-bit 40-MSPS dual DAC with four integrated voltage output control DACs. This DAC can be used for I and Q in wireless applications. The additional four voltage output control DACs provide wireless system cost savings by allowing the designer to control transmit and receive path gain and adjust filter and local oscillator frequencies. The use of these four control DACs simplifies the system design, provides flexibility and can provide overall system cost savings.

#### Key Features:

- Dual 12-bit, 40-MSPS current output DACs
- $\bullet$  Four 12-bit  $V_{out}$  DACs for signal path control
- Ultra low power: 29 mW
- Adjustable full-scale output: 0.5 mA to 2 mA
- 3.3-V supplies
- Power down mode: 25  $\mu W$
- Budgetary pricing: U.S. \$7.95/1 KU
- Packaging: 48-lead TQFP

#### LOW-COST, SINGLE DAC FAMILY DAC904/DAC902/THS5671A/THS5661A

Get samples, datasheets, and EVMs at: www.ti.com/sc/device/partnumber

Replace partnumber in URL with dac904, dac902, ths5671a, or ths5661a

The DAC90x and THS56x1A families are pin-compatible, single DACs with 8-bit, 10-bit, 12-bit, and 14-bit options. These are the lowest-cost DACs available on the market.

#### Key Features:

- Update rate of 165 MSPS (DAC90x); 125 MSPS (THS56x1A)
- Analog supply of 5 V; digital supply of 3 V or 5 V
- On-chip, 1.2-V reference
- Set-up and hold times of 1 ns
- Twos complement or binary input code format (THS56x1A)
- Differential current outputs of 2 mA to 20 mA
- SFDR > 60 dBc at 27.4 MHz IF at 165 MSPS
- Low power: 175 mW at 5 V
- Packaging: 28-pin SOIC, 28-pin TSSOP (10- and 8-bit versions are also available for both families)

# **General Overview**

### QUADRATURE MODULATORS

TRF3701/TRF3702

#### Get datasheets at: www.ti.com/sc/device/partnumber Replace partnumber in URL with trf3701 or trf3702

TRF3701 and TRF 3702 are low-noise guadrature-direct modulators capable of converting complex input signals from 0-250 MHz IF up to RF. An internal analog combiner sums the real and imaginary components of the RF output. The modulators are implemented as a double-balanced mixer. An internal LO phase splitter accommodates a single LO input.

#### **Key Features:**

- TRF3701: IF to 900 MHz
- TRF3702: IF to 2 GHz
- Typical optimized carrier suppression > 50 dBc
- Typical optimized sideband suppression > 50 dBc
- Typical noise floor; -157 dBm/Hz at 700 to 900 MHz

- 5-V single supply

#### INTEGER-N RF PLL SYNTHESIZER TRF3750



Product

Preview

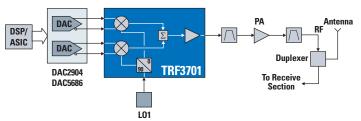
Get samples, datasheets, app reports and EVMs at: www.ti.com/sc/device/trf3750

The TRF3750 is frequency synthesizer that can be used to implement local oscillators (LO) up to 3 GHz in the RF upconversion and downconversion chains of wireless transmitters and receivers. A complete Phase Locked Loop (PLL) can be implemented using an external loop filter and a Voltage-Controlled Oscillator (VCO) together with the TRF3750. The very wide frequency range simplifies system complexity and reduces cost.

#### **Key Features:**

- Supports operation up to 3 GHz
- Supply voltage of 2.7 V to 5.5 V
- Programmable charge pump currents
- Programmable anti-backlash pulse width
- Analog and digital lock detect
- Low phase noise
- Extended VCO control range through independent VCP supply
- Hardware and software power down
- Packaging: 16-lead TSSOP

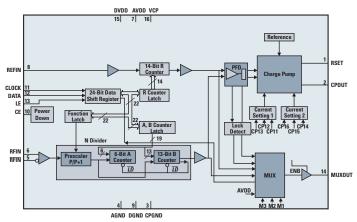
TRF3701 and TRF3702 in Direct Upconversion Architecture



#### Applications:

- Cellular BTS
  - CDMA: W-CDMA, CDMA2000, IS-95
- TDMA: GSM, IS-136, EDGE/UWC-136
- Wireless local loop
- Wireless LAN 802.11
- LMDS, MMDS

TRF3750 Internal Block Diagram



#### Applications:

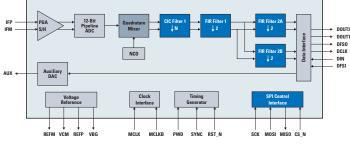
- Cellular BTS:
  - CDMA: W-CDMA, CMDA2000, IS-95
  - TDMA: GSM, IS-136, EDGE/UWC-136
- Portable wireless communications equipment
- Wireless local loop
- Communications test equipment

Logic

**Timing & Interface** 



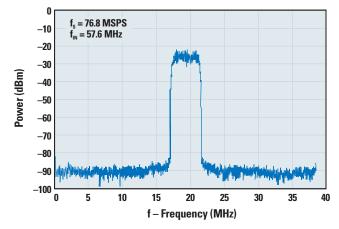
Detailed AFE8201 Block Diagram



Applications:

Receivers

W-CDMA	Single-Carrier	Measurement
00000	enigie eanier	i i i o a o a i o i i o i i o i i o



#### Applications:

- Performance supports across cellular standards
  W-CDMA / CDMA2000 / GPRS / EDGE / GSM / IS-95
- Wireless local loop / LMDS / MMDS
- Point-to-point microwave

#### 12-BIT ADC WITH INTEGRATED DDC AFE8201

Get samples, datasheets, app reports and EVMs at: www.ti.com/sc/device/afe8201

The AFE8201 is an 80-MSPS, 12-bit ADC that includes a digital downconverter (DDC) and user-programmable digital filters. It is designed to sample IF signals and digitally mix, filter, and decimate the signals to baseband. An integrated 12-bit DAC is included to control the gain of the IF block. This highly integrated device simplifies and reduces costs for receiver applications.

#### Key Features:

- 12-bit, 80-MSPS ADC
- Integrated digital down converter
- 32-bit NCO
- Digital filters
- User-programmable coefficients
- McBSP interface for TI DSPs
- 12-bit control DAC
- Budgetary pricing: U.S. \$25/1 KU

#### LOWEST-POWER, LOWEST-COST ADC FOR BTS RECEIVERS ADS5410

Get samples, datasheets, and EVMs at: www.ti.com/sc/device/ads5410

The 12-bit, 80-MSPS ADC offers the lowest power at this performance level. It is a low-cost alternative to expensive 14-bit ADCs and can be implemented in cost-reduction programs for existing systems or startup of 3G systems.

#### Key Features:

- 12 bit, 80 MSPS
- SFDR: 75 dB at 100-MHz IF
- SNR: 60 dB at 70-MHz IF
- Digital outputs from 1.6 V 3.3 V in 2s complement
- Flexible clocking: Single-ended or differential
- Power: 360 mW

50-MHz TO 400-MHz CASCADEABLE

Get samples, datasheets, app reports and EVMs at:

Replace partnumber in URL with ths9000 or ths9001

The THS9000 and THS9001 are medium power, cascadeable, gain block optimized for 50-MHz to 400-MHz IF frequencies. The

input and output return loss from 50 MHz to 325 MHz with

amplifiers incorporate internal impedance matching to 50  $\Omega$ . The part mounted on the standard EVM achieves greater than 15 dB

 $V_s = 5 \text{ V}$ ,  $R_{BIAS} = 237 \Omega$ ,  $L_{COL} = 470 \text{ nH}$ . Design requires only 2 dc blocking capacitors, 1 power supply bypass capacitor, 1 RF

choke, and 1 bias resistor. The THS9000 comes in a very small

2×2-mm leadless MSOP package, and the THS9001 comes in a

6-pin SOT23 package. These devices make excellent choices for driving SAW filters, buffering LOs, or general-purpose IF amplifiers.

# Signal Chain

#### Key Features:

- OIP3: 37 dBm at 300 MHz
- Gain: 15.5 dB

IF AMPLIFIERS

www.ti.com/partnumber

THS9000/THS9001

- Noise figure: 4.0 dB at 300 MHz
- 1 dB compression: 20.6 dBm

#### HIGH-SPEED, FULLY DIFFERENTIAL OP AMP THS4502/THS4503

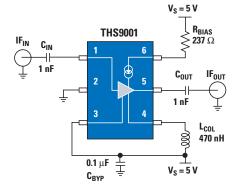
Get samples, datasheets, and EVMs at: www.ti.com/sc/device/partnumber Replace partnumber in URL with ths4502 or ths4503

The THS4502, featuring power-down capability, and the THS4503, without power-down capability, set new performance standards for fully differential amplifiers with unsurpassed linearity, supporting 14-bit operation through 40 MHz.

#### Key Features:

- + 370-MHz bandwidth (V\_{CC} =  $\pm 5$  V, R\_f = 392  $\Omega,~G$  = 0 dB)
- Slew rate: 2800 V/µs
- $OIP_3 = +38 \text{ dBm at } 30 \text{ MHz} (G = 12 \text{ dB})$
- NF = 25 dB (G = 12 dB)
- Differential input/differential output
- Output common-mode voltage control
- Balanced architecture rejects common-mode noise and reduces even order harmonic distortion

#### THS9001 Block Diagram

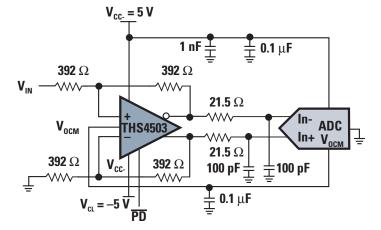


- $V_S = 3 V$  to 5 V
- $I_S$  is adjustable
- Packaging: 6-lead (leadless) MSOP, SOT23-6

#### Applications:

- IF amplifier
- TDMA: GSM, IS-136, EDGE/UWE-136
- CDMA: IS-95, UMTS, CDMA2000
- Wireless local loop
- Wireless LAN: IEEE 802.11
- Radio links

#### THS4503 Block Diagram

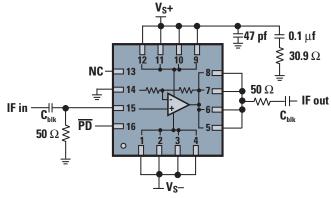


#### Applications:

- Single-ended to differential conversion
- Differential ADC driver
- Active differential anti-alias filter

**Timing & Interface** 

THS4302 Block Diagram

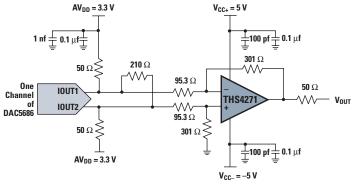


#### Single-Supply IF Amplifier Application Circuit, G = 8 dB into 50- $\Omega$ Load

#### Applications:

- High-frequency signal processing
- LO drive
- High-frequency ADC drivers
- High-speed DAC buffers

Differential to Single-Ended Conversion of High-Speed DAC Output



For test data, see DAC5686 graph, page 11

#### Applications:

- Low-noise differential to single-ended conversion
- Differential line receiver
- Active anti-alias filtering

#### FIXED-GAIN, HIGH-SPEED OP AMP WITH POWER DOWN THS4302

Get samples, datasheets, and EVMs at: www.ti.com/sc/device/ths4302

The THS4302 is an ultra-low-distortion, single-supply-operation, wide-bandwidth, high-speed amplifier ideal for use with high-resolution data converters. These voltage feedback amplifiers can operate from a single 5-V power supply while delivering a performance level of -88 dBc third-order intermodulation distortion (IMD<sub>3</sub>) at 100 MHz.

#### Key Features:

- 2.4-GHz bandwidth
- G = 14 dB (non-inverting)
- Slew rate: 5500 V/μs
- NF = 16 dB
- $\text{OIP}_3$  = 39 dBm at 100 MHz (R\_L = 100  $\Omega)$
- High output drive,  $I_0 = \pm 180 \text{ mA}$  (typ)
- $V_{\rm S} = 3 \,\mathrm{V}$  to  $5 \,\mathrm{V}$
- Evaluation module available
- Packaging: Leadless packages

#### ULTRA-LOW-DISTORTION, HIGH-SPEED OP AMPS WITH SHUTDOWN THS4271/THS4275

Get samples, datasheets, and EVMs at: www.ti.com/sc/device/partnumber

Replace partnumber in URL with ths4271 or ths4275

The THS4271 and THS4275 are ultra-low distortion and noise, single-ended 5-V operation, wide-bandwidth, high-speed amplifiers. They are ideal for use with high-resolution data converters. These voltage-feedback amplifiers have a power supply range of 4.5 V to 15 V while delivering a performance level of -90 dB of harmonic distortion (THD) at 30 MHz.

#### Key Features:

- HD2 = -92 dBc (f = 30 MHz, R<sub>L</sub> = 150  $\Omega$ , V<sub>O</sub> = I<sub>VPP</sub>)
- HD3 = -95 dBc (f = 30 MHz, R<sub>L</sub> = 150  $\Omega$ , V<sub>O</sub> = I<sub>VPP</sub>)
- $3-nV/\sqrt{Hz}$  input noise voltage
- 1.4-GHz bandwidth (-3 dB, G = +1)
- Slew rate: 1000 V/μs
- 25-ns settling time (0.1%)
- High output drive, I<sub>O</sub> = 160 mA (typ)
- Wide range of power supplies:  $\pm 2.5$  V to  $\pm 7.5$  V

#### 2-GHz, LOW DISTORTION, CURRENT FEEDBACK AMPLIFIER THS3202

Get samples, datasheets, app reports and EVMs at: www.ti.com/sc/device/ths3202

The THS3202 is a low-distortion, high slew rate op amp ideally suited for applications driving loads sensitive to distortion at high frequencies. It provides well-regulated AC performance characteristics with a power supply range of 6.6 to 15 V. The device's low differential gain/phase error makes it ideal for video line driver applications, test and measurement systems and RF and IF amplifier stages.

#### Key Features:

- Unity-gain bandwidth: 2 GHz
- High slew rate: 9000 V/µs
- IMD<sub>3</sub> at 120 MHz: -89 dBc (ref measurement circuit)
- OIP3 at 120 MHz: 43 dBm (ref measurement circuit)
- NF = 17.5 dB (ref measurement circuit)
- High output current: ±115 mA into 20  $\Omega$   $\text{R}_{\text{L}}$
- Power supply voltage range: 6.6 V to 15 V
- Packaging: 8-lead SO, 8-lead MSOP

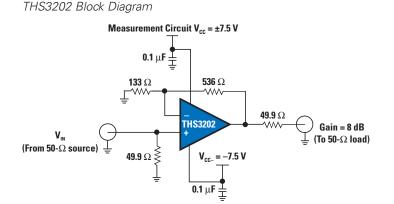
#### 3–9-GHz GBW, ULTRA-LOW NOISE, VOLTAGE FEEDBACK OP AMPS OPA846/OPA847

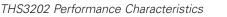
Get samples and datasheets at: www.ti.com/sc/device/partnumber Replace partnumber in URL with opa846 or opa847

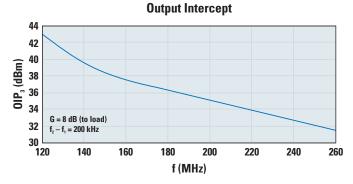
The OPA847 combines very-high-gain bandwidth and large signal performance with an ultra-low input noise voltage (0.85 nV/ $\sqrt{Hz}$ ), while using only 18 mA of supply current. As a voltage gain stage, the OPA847 is optimized for a flat frequency response at a gain of +20 V/V and is stable down to gain as low as +12 V/V. New external compensation techniques allow the OPA847 to be used at any inverting gain with excellent frequency response control. Using this technique in a differential ADC interface application, as shown, can deliver one of the highest dynamic range interfaces available.

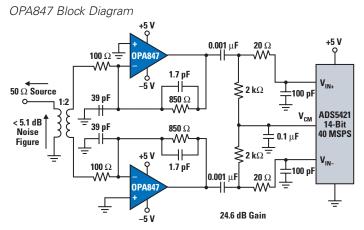
Device	Minimum Operating Gain (V/V)	GBW (MHz)	Input Noise Volta <u>ge</u> nV/√Hz	Offset Voltage Drift (0 to 70°C) max (mV/°C)	Offset Current Drift (0 to 70°C) max (nA/°C)	Price Starts at 1K
0PA842	1	200	2.60	4	2	\$1.45
0PA843	3	800	2.00	4	2	\$1.49
OPA846	7	1750	1.20	1.5	2	\$1.59
0PA847 <sup>†</sup>	14	3800	0.85	1.5	2	\$1.89
0PA656*	1	230	7.00	12	0.9	\$3.19
0PA657*	7	1600	4.80	12	0.9	\$3.59

<sup>\*</sup>JFET input trimmed offset drift low grade specifications shown. High grade available with <6  $\mu V/^{\circ}C$  max. drift.

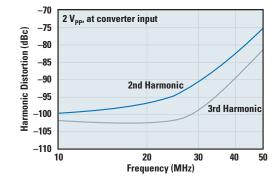








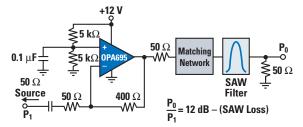
Differential OPA847 Driver Distoration



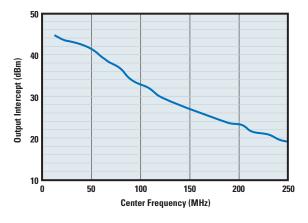
#### Applications:

- High dynamic range ADC preamps
- Wideband, high gain amplifiers

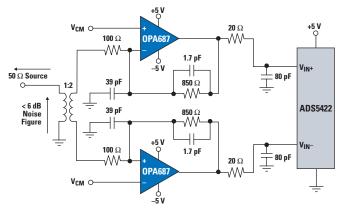
Low Distortion, 12-dB Gain SAW Driver

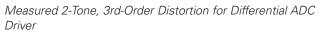


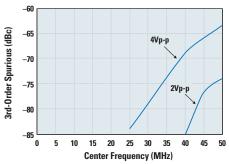
2-Tone 3rd-Order Intermodulation Intercept



Ultra-High Dynamic Range Differential Input ADC Driver







#### ULTRA-WIDE BAND, CURRENT FEEDBACK OP AMP WITH DISABLE OPA695

Get samples and datasheets at: www.ti.com/sc/device/opa695

The OPA695 is a very-high bandwidth, current-feedback op amp that combines 4200-V/ $\mu$ s slew rate and low-input voltage noise to deliver a precision, low-cost, high-dynamic range IF amplifier. Optimized for high-gain operation, the OPA695 is ideally suited to buffering SAW filters.

#### Key Features:

- Gain = +2 bandwidth: 900 MHz
- Gain = +8 bandwidth: 420 MHz
- Ultra-high slew rate: 4200 V/µs
- 3rd order intercept: > 40 dBm (f < 50 MHz)

#### Applications:

- Very wideband ADC driver
- Video line driver
- ARB waveform output driver

#### WIDEBAND, ULTRA-LOW-NOISE, VOLTAGE FEEDBACK AMPLIFIER OPA687

Get samples and datasheets at: www.ti.com/sc/device/opa687

The OPA687 combines a very high gain bandwidth and large signal performance with an ultra-low input noise voltage while dissipating only 18-mA supply current. The low input noise voltage and its very-high, two-tone intercept can be used as a fixed-gain IF amplifier.

#### Key Features:

- High gain bandwidth: 3.8 GHz
- Low input voltage noise: 0.95 nV/vHz
- Stable for  $G \ge 12$
- Two-tone, 3rd-order intercept: 43 dBm

#### Applications:

- RF/IF amplifier
- Low-distortion ADC driver

16-BIT RISC FLASH MCU FOR ONLY \$0.99

Get samples, datasheet, application reports, and EVMs at:

A new class of low-power, advanced RISC-architecture MCUs,

micro-amps at 1 MHz and feature TI's analog and digital signal

TI's family of Flash-based MSP430 MCUs consume just 250

# **General Overview**

### Key Features:Ultra-low-po

MSP430F11x1

www.ti.com/sc/msp430

processing expertise.

- Ultra-low-power consumption, 250- $\mu A$  active, 0.8- $\mu A$  standby at 2.2 V (typ)
- 16-bit RISC architecture enables new applications at a fraction of the code size
- Integrated analog comparator is ideal for precise mixed-signal measurement
- Multifunctional, 16-bit multichannel timer with PWM, capture, and compare capability
- In-system programmable Flash permits last-minute code changes, field upgrades, and data logging to Flash
- The MSP-FET430X110 offers a completely integrated development environment for only U.S. \$49
- New, small 4×4-mm QFN packaging available 4Q 2003

#### 16-BIT RISC FLASH MCU WITH INTEGRATED 12-BIT ADC, MULTIPLIER, AND USARTs MSP430F14x

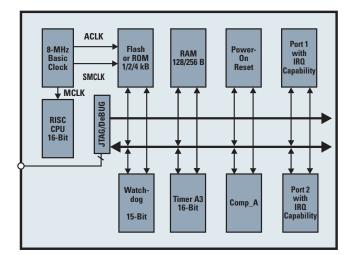
Get samples, datasheets, application reports, and EVMs at: www.ti.com/sc/msp430

Experience the ultimate SoC solution for low-power applications. The MSP430F14x features the combination of ultra-low power consumption and integrated high-performance analog peripherals ideal for cost, power, and space-sensitive applications.

#### Key Features:

- Ultra-low power consumption: 250-µA active mode, 0.8-µA standby mode at 2.2 V (typ)
- 16-bit RISC architecture enables new applications at a fraction of the code size
- High-performance integrated analog and digital peripherals including a 200-ksps, 12-bit A/D converter, to reduce system cost and speed time-to-market
- Serial communication interface (USART) functions as asynchronous UART or synchronous SPI interface
- Two 16-bit PWM timers allow highly flexible multichannel capture and compare
- In-system programmable Flash permits last-minute code changes, field upgrades, and data logging to Flash
- The MSP-FET430P140 offers a completely integrated development environment for only U.S. \$99

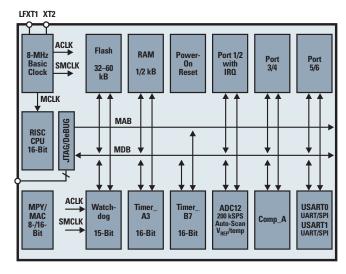
#### MSP430F11x1 Block Diagram



#### Applications:

- Monitoring and control
- Can support initialization of CDC7005 clock synchronizer

#### MSP430F14x Block Diagram



#### Applications:

• Monitoring and control

Logic

#### **HIGH-SPEED AMPLIFIERS**

	Part Nur	nber		9	chitec S		Shutdown	Sup	ply Vol	tage	A <sub>CL</sub> Min	BW	Slew Rate	•	Time to 0.01%	THD 1 MHz		rential Phase	V <sub>N</sub>	V <sub>OS</sub> mV	Ι <sub>b</sub> μΑ	I <sub>s/amp</sub> mA	I <sub>OUT</sub> mA	
Single	Dual	Triple	Quad	E E E		C-St	Shu 3	V 5 V	/ ± 5 \	± 15 V			V/µs	ns (ty	yp)	dBc (typ)	%/	D	V/√Hz	(max)	(max)	(typ)	(typ)	Price <sup>1</sup>
	Feedback	Up Amps							•	•	1	270	400	40		70	0.04	0.15	10 5	0	E	7.0	100	2.10
THS4001	THS4012			•				•	•		1	270	400 310	40	-	-72	0.04	0.15	12.5	8	5	7.8	100	2.19
				•					•	•	10	290		37	90	-80	0.01	0.01	7.5	6	6	7.8	110	2.29/3.81
	THS4022			•					•	•	10	350	470	40	145	-72	0.02	0.08	1.5	2	6	7.8	100	1.67/2.79
	THS4032			•					•	•	2	100	100	60	90	-90	0.015		1.6	2	6	8.5	90	2.23/3.68
	THS4042			•		·			•		1	165	400	120	250	-89	0.01	0.01	14	10	6	8	100	1.25/2.49
	THS4052			•					•	•	1	70	240	60	130	-89	0.01	0.01	14	10	6	8.5	100	1.20/1.55
	THS4062			•					•	•	1	180	400	40	140	-72	0.02	0.02	14.5	8	6	7.8	115	1.52/1.92
	THS4082			•				*	*	•	1	175	230	43	233	-79	0.01	0.05	10	7	6	3.4	85	1.79/2.78
THS4271				•			×	^ ×	~		1	1400	970	25	38	<-120	0.007		2.8	10	18	22	90	2.69
THS4275				•			*	*	*		1	1400	970	25	38	<-120	0.007	0.004	2.8	10	18	22	90	2.69
THS4601				•	•				•	•	1	440	100	135	170	-77			5.4	4	100 pA	10	80	9.95
0PA355	0PA2355	UPA3355		•	•		•	• •			1	450	300	30	120	-81	0.02	0.05	5.8	9	50 pA	8.3	60	1.20/1.99/2.82
0PA356	0PA2356			•	•			• •			1	450	300	30	120	-81	0.02	0.05	5.8	9	50 pA	8.3	60	1.10/1.90
OPA627				•	•				•	•	1	16	55	450	550	-	-	-	4.5	0.1	5 pA	7	45	8.28
OPA637				•	•				•	•	2	80	135	300	450	-	-	-	4.5	0.1	5 pA	7	45	8.28
OPA642				•					•		1	450	380	11.5	13	-95	0.007	0.008	2.3	1	45	22	60	3.75
	0PA2652			•					•		1	700	335	-	-	-77	0.05	0.03	8	7	15	11	140	1.19
OPA655				•	•				•		1	400	290	8	17	-92	0.006	0.009	6	2	125 pA	25	60	9.13
OPA656				•	•				•		1	500	290	10	-	-85	0.02	0.05	7	1.8	20 pA	14	70	5.85
OPA657				•	•				•		7	350	700	10	-	-78	-	-	4.8	1.8	20 pA	14	70	7.29
OPA686	OPA2686			•				•	•		7	250	600	16	18	-83	0.02	0.02	1.3	1	17	12.4	80	2.89
OPA687											12	600	900	15	17	-85	-	-	0.95	1	33	18.5	80	3.49
OPA688				•				•	•		1	530	1000	-	7	-	0.02	0.01	6.3	6	12	15.8	100	2.65
OPA689				•				•	•		4	280	1600	-	7	-64	0.02	0.01	4.6	5	12	15.8	100	2.95
OPA690	0PA2690	0PA3690		•			•	•	•		1	500	1700	8	-	-83	0.06	0.01	4.5	4	8	5.5	190	1.50/2.32/3.19
	0PA2822			•				•	٠		1	400	170	32	-	-95	0.02	0.03	2	1.2	12	4.8	150	2.17
THS4303								•			5	2500	1000	5		-92	-	-	2.4	0.5	6	34	100	-
THS4304								•			1	2500	1000	5		-92	-	-	2.4	0.5	6	18	100	-
OPA842								•	•		1	350	400	15 ns		-	0.003	0.006	2.6	0.3	20	20.2	±100	1.35
OPA843								•	•		3	500	1000	7.5 ns	-	-	0.001	0.012	2	0.3	20	20.2	±100	1.39
<b>OPA846</b>								•	•		7	500	625	10 ns	-		0.02	0.02	1.2	0.15	10	12.6	±80	1.59
OPA847								•	•		12	600	950	10 ns	-		-	-	0.85	0.1	19	18.1	100/'-75	1.49
THS9000								• •			5.8	500	-	-	-	-	-	-	0.6	-	-	100	-	-
THS9001								• •			5.8	500	-	-	-	-	-	-	0.6	-	-	100	-	-
OPA698								•	•		1	450	1100	8 ns			0.012	0.008	5.6	2	3	15.5	±120	1.79
OPA699								•	•		6	285	1500	7 ns					4.1	0.5	8	15.5	±100	1.85
Current-F	eedback (	Op Amps																						
THS3001				•					•	•	1	420	6500	40	-	-96	0.01	0.02	1.6	3	10	7.5	120	3.37
THS3061	THS3062			•					•	•	1	300	7000	30	125	-	0.02	0.01	2.6	0.7	2	8.3	145	2.95/4.25
	THS3112			•					•	•	1	110	1550	63	-	-78	0.01	0.011	2.2	8	23	4.9	270	3.03
	THS3115			•			•		•	•	1	110	1550	63	-	-78	0.01	0.011	2.2	8	23	4.9	270	3.03
	THS3122			•					•	•	1	160	1550	64	-	-80	0.01	0.011	2.2	6	23	8.4	440	3.75
	THS3125			•			•		•	•	1	160	1550	64	-	-80	0.01	0.011	2.2	6	23	8.4	440	3.75
DPA658	OPA2658			•					•		1	900	1700	11.5	15	-82	0.025	0.02	2.7	4.5	18	4.5	80	1.95/3.12/4.99
OPA684	OPA2684	OPA3684/ OPA4684		•				•	•		1	170	780	-	-	-82	0.04	0.02	3.7	1.5	5	3.4	160	1.3/1.97

<sup>1</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

Preview devices are listed in blue.

New devices are listed in red. Continued on next page

#### **HIGH-SPEED AMPLIFIERS (CONTINUED)**

				4		tectur						A <sub>CL</sub>	1	Slew	Settling	Time to	THD	Diffe	rential		V <sub>OS</sub>	I <sub>b</sub>	I <sub>s/amp</sub>	Iout	
	Part Nu	mber			Diff I/O	<	C-Stable Shutdown	5	Suppl	y Volt	age		BW	Rate		0.01%	1 MHz	Gain/	Phase	V <sub>N</sub>	mV	μÅ	mA	mA	
Single	Dual	Triple	Quad	CFB CFB		PGA	S Ē	3 V	5 V	± 5 V	± 15 V	V/V	MHz	V/µs	ns (t	yp)	dBc (typ)	%	6/°	V/√Hz	(max)	(max)	(typ)	(typ)	Price <sup>1</sup>
Current-Feedback Op Amps (Continued)        THS3201/      THS3202      •      •      1      1800      5100      19      118      -65      0.004      0.006      1.65      4      85      15      115      1.87/																									
THS3201/	THS3202				•				•	•		1	1800	5100	19	118	-65	0.004	0.006	1.65	4	85	15	115	1.87/2.89
0PA685				•			•		•	٠		1	1200	4200	3	4	-80	0.1	0.01	1.7	3.5	90	12.9	90	1.89
OPA691	OPA2691	OPA3691		•			•		•	•		1	400	2100	10	-	-81	0.001	0.01	2.5	2.5	35	5.1	190	1.45/2.32/3.15
<b>OPA693</b>									•	٠		2	800	2400	3		-85	0.02	0.01	1.6	0.7	10	13	120	1.35
<b>OPA695</b>									•	•		1	1200	2400	3		-85	0.02	0.01	1.6	0.7	10	13	120	-
THS3201										•		1	1800	6200	20		-85	0.006	0.03	1.65	0.7	13	14	115	1.59
Fixed-Ga	in Amplifi	ers																							
THS4302							•	•	•			5	2400	5500	1.5	6	<-120			2.8	4.25	10	37	180	1.97
BUF634									•	٠	•	1	180	2000	200	-	-	0.4	0.1	4	100	20	15	250	2.84
OPA633										•	•	1	260	2500	50	-	-	0.1	0.1		15	35	21	100	5.15
0PA692		0PA3692					•		•	٠		1	225	2000	8	-	-	0.07	0.02	1.7	0.5	5	5.1	190	1.35/2.98
THS9000								٠	٠			6	900												1.00
THS9001								•	•			6	900												1.00
Variable-	Gain Amp	lifiers																							
THS7530						•	•		•				230	>1750	-	-	-63			1.27		44	35	20	3.65
<sup>1</sup> Suggeste	ed resale	price in L	J.S. dolla	rs in q	uanti	ties of	<sup>c</sup> 1,000	).														Previ	iew devi	ices are	e listed in blue

New devices are listed in red.

#### **D/A CONVERTERS**

Device Name	Resolution (Bits)	Supply (V)	Update Rate (MSPS)	Settling Time (ns)	Number of DACs	Power Typ (mW)	DNL Max (±LSB)	INL Max (±LSB)	Pin/ Package	Price <sup>1</sup>
DAC904	14	3.0 to 5.0	165	30	1	170	1.75	2.5	28 SOP 28 TSSOP	6.25
THS5671A	14	3.0 to 5.0	125	35	1	175	3.5	7	28 SOP 28 TSSOP	8.00
DAC902	12	3.0 to 5.0	165	30	1	170	1.75	2.5	28 SOP 28 TSSOP	6.25
THS5661A	12	3.0 to 5.0	125	35	1	175	2.0	4	28 SOP 28 TSSOP	6.25
DAC900	10	3.0 to 5.0	165	30	1	170	0.5	1	28 SOP 28 TSSOP	4.25
THS5651A	10	3.0 to 5.0	125	35	1	175	0.5	1	28 SOP 28 TSSOP	4.25
DAC2904	14	3.3 to 5.0	125	30	2	310			48TQFP	20.19
DAC2902	12	3.3 to 5.0	125	30	2	310	2.5	3	48 TQFP	15.41
DAC2900	10	3.3 to 5.0	125	30	2	310	1	1	48 TQFP	9.19
DAC5675	14	3	400	5	1	820	2	4	48 HTQFP	29.75
DAC5686	14	1.8/3.3	500	12	2	400	TBD	TBD	100 HTQFP	42.00
DAC2932	12	2.7 to 3.3	40	25	2	29	0.5	2	48 TQFP	7.95
DAC5674	12	1.8/3.3	400	20	1	420	2	3.5	48 HTQFP	21.00

<sup>1</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

#### Preview devices are listed in blue.

#### **A/D CONVERTERS**

Device Name	Resolution (Bits)	Sample Rate (MSPS)	Supply (V)	Analog Inputs	Power Typ (mW)	Analog Input BW (MHz)	DNL Max (±LSB)	INL Max (±LSB)	SNR (dB)	Pin/ Package	Price <sup>1</sup>
ADS5410	12	80		1	360	1000	1	2	67	48 TQFP	23.00
ADS5422	14	62	5	1	1200	300	1		72	64 ΤΩFP 64 LΩFP	29.00
ADS809	12	80	5	1	880	1000	1.7	6	65	48 TQFP	23.75
AFE8201*	12	80	2.7 to 3.3	1	450	1000	1	2	67	48 TQFP	25.00

<sup>1</sup>Suggested resale price in U.S. dollars in quantities of 1,000. \* AFE8201 integrates programmable DDC, PG4, and Control DAC. Directly interfaces to TI TMS320C5000™ and TMS320C6000™ DSP platforms with McBSP port.

#### **DIGITAL DOWNCONVERTERS/UPCONVERTERS (DDC/DUC)**

Device	Max Clock Rate	Conversion Type	Narrowband Channels <sup>2</sup>	Wideband Channels <sup>3</sup>	Automatic Gain Control	Input Resolution	Output Resolution	SFDR	Power (max) / Channel	Special Features	Price <sup>1</sup>
GC5016	150	Up and/or down	4	4	V	16	16	115	250	RSSI meters, programmable filters, real or complex data formats	65.00
GC4016	100	Down	4	2		16	24	115	115	Resampler, serial, or parallel output formats	48.00
GC4116	105	Up	4	2	NA	16	22	115	150	Resampler, IS-95/CDMA phase equalization	48.00
GC1012B	100	Down	-	1		12	16	75	850	Fixed decimate by 2, 4, 8, 16, 32, or 64	-

<sup>1</sup>Suggested resale price in U.S. dollars in quantities of 1,000. <sup>2</sup>DAMPS, GSM, IS-95, CDMA2001X

<sup>3</sup>UMTS, DOCSIS, QAM

#### MSP430 ULTRA-LOW-POWER MICROCONTROLLERS

Device <sup>1</sup>	Program (kB)	SRAM	I/O	WDT	Timer A	Timer B	USART	l²C	SVS	BOR	MPY	Comp A	ADC	DAC	Pins/Package	Price <sup>2</sup>
Flash-Based F1>	x Family <sup>3</sup>	(V <sub>CC</sub> 1.8 1	to 3.6 V	/)												
MSP430F1101A	1	128	14	~	V							~	Slope		20 DGV, DW, PW, 24 RGE	0.99
MSP430C1101	1	128	14	V	V							V	Slope		20 DW, PW, 24 RGE	0.60
MSP430F1111A	2	128	14	~	~							V	Slope		20 DGV, DW, PW, 24 RGE	1.34
MSP430C1111	2	128	14	~	V							~	Slope		20 DW, PW, 24 RGE	1.10
MSP430F1121A	4	256	14	~	~							~	Slope		20 DGV, DW, PW, 24 RGE	1.66
MSP430C1121	4	256	14	~	V							~	Slope		20 DW, PW, 24 RGE	1.34
MSP430F1122	4	256	14	~	~					~			5-ch ADC10		20 DW, PW, 32 RHB	1.99
MSP430F1132	8	256	14	~	V					~			5-ch ADC10		20 DW, PW, 32 RHB	2.23
MSP430F122	4	256	22	~	~		1					~	Slope		28 DW, PW, 32 RHB	2.11
MSP430F123	8	256	22	<b>v</b>	V		1					~	Slope		28 DW, PW, 32 RHB	2.26
MSP430F1222	4	256	22	~	V		1			~			8-ch ADC10		28 DW, PW, 32 RHB	2.36
MSP430F1232	8	256	22	<b>v</b>	~		1			~			8-ch ADC10		28 DW, PW, 32 RHB	2.49
MSP430F133	8	256	48	~	~	V	1					~	8-ch ADC12		64 PM, RTD, PAG	2.98
MSP430F135	16	512	48	~	V	V	1					~	8-ch ADC12		64 PM, RTD, PAG	3.59
MSP430C1331	8	256	48	V	V	~	1					V	Slope		64 PM, RTD	1.97
MSP430C1351	16	512	48	<b>v</b>	V	V	1					~	Slope		64 PM, RTD	2.27
MSP430F147	32	1024	48	~	~	V	2				V	~	8-ch ADC12		64 PM, RTD, PAG	5.01
MSP430F1471	32	1024	48	<b>v</b>	V	V	2				V	~	Slope		64 PM, RTD, PAG	4.60
MSP430F148	48	2048	48	V	V	~	2				V	V	8-ch ADC12		64 PM, RTD, PAG	5.71
MSP430F1481	48	2048	48	<b>v</b>	V	~	2				V	V	Slope		64 PM, RTD	5.30
MSP430F149	60	2048	48	V	V	~	2				V	V	8-ch ADC12		64 PM, RTD, PAG	6.03
MSP430F1491	60	2048	48	V	V	~	2				V	V	Slope		64 PM, RTD	5.60
MSP430F155 <sup>4</sup>	16	512	48	V	V	~	1	~	V	V		V	8-ch ADC12	2-ch DAC12	64 PM	4.95
MSP430F156 <sup>4</sup>	24	1024	48	V	V	~	1	~	V	V		V	8-ch ADC12	2-ch DAC12	64 PM	5.65
MSP430F157 <sup>4</sup>	32	1024	48	V	V	~	1	~	V	V		V	8-ch ADC12	2-ch DAC12	64 PM	5.85
MSP430F167 <sup>4</sup>	32	1024	48	V	V	~	2	~	V	V	V	V	8-ch ADC12	2-ch DAC12	64 PM	6.73
MSP430F168 <sup>4</sup>	48	2048	48	V	V	~	2	~	V	V	V	V	8-ch ADC12	2-ch DAC12	64 PM	7.45
MSP430F169 <sup>4</sup>	60	2048	48	~	V	~	2	~	V	V	V	V	8-ch ADC12	2-ch DAC12	64 PM	7.95
MSP430F1610 <sup>4</sup>	32	5120	48	V	V	~	2	~	V	V	V	V	8-ch ADC12	2-ch DAC12	64 PM	8.45
MSP430F1611 <sup>4</sup>	48	10240	48	V	V	V	2	~	V	V	V	V	8-ch ADC12	2-ch DAC12	64 PM	8.95

 $^{1}C = ROM, F = Flash$ 

<sup>2</sup>Suggested resale unit price in U.S. dollars in quantities of 1,000.

<sup>3</sup>All devices support industrial temperature range.

<sup>4</sup>Planned release 10 2004.

# **General Overview**

Signal Chain

**TIMING AND INTERFACE PRODUCTS** 

Wireless Infrastructure (WI) systems will accommodate a wider range of technologies than ever before as the industry moves from 2G to 2.5G and 3G. Advanced wireless technologies like Bluetooth<sup>™</sup> personal area networking (PAN), wireless local area networking (WLAN) with IEEE 802.11 technology, and leading wireless protocols like GSM, CDMA, and UMTS all place higher demands on WI systems for greater processing performance without jeopardizing power consumption or cost characteristics.

Designers realize that the increased data rates must be supported by base station and controller backplanes and the interconnections between these systems. Typically, this means the standard backplane either has to speed up or become wider, moving from 16-bit to 32-bit and beyond.

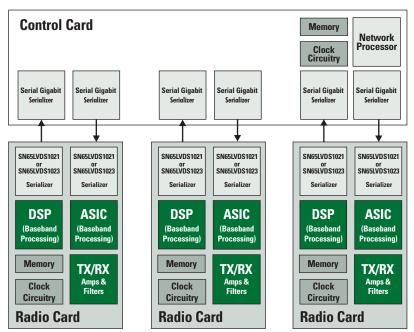
TI's timing and interface components simplify the generation of timing signals that are used to synchronize system activity and meet today's stringent clock-signal timing requirements. A wide selection of high-fan-out drivers, repeaters, and translators provide benefits like low propagation delay, low jitter, and reduced skew, in addition to driving high-performance clocking systems.

TI timing and interface products that support wireless infrastructure applications include:

- Serializer/Deserializer (SerDes) devices ranging from 100 Mbps to 3.125 Gbps, based on LVDS or LVPECL technology
- Repeaters, translators, and multiplexers transmitting at speeds up to 2.0 Gbps with less than 65-ps total jitter
- Single-ended and differential bi-directional transceivers supporting multipoint topologies
- Clock solutions that buffer, synchronize, divide, and multiply with low-phase noise
- PHY and link 1394 (FireWire<sup>™</sup>) solutions<sup>\*</sup>
- Low-noise GTLP solutions

\*See www.ti.com/connectivity for information

100-MHz to 600-MHz, 10-Bit LVDS Serializer/Deserializer (SerDes) Chipsets



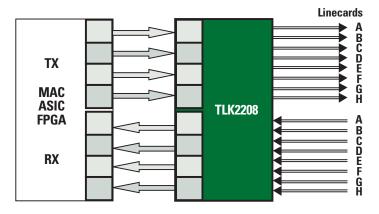
#### TO KNOW MORE 🕨

For detailed information about timing and interface ICs for wireless infrastructure:

Transceivers and receivers	25
Clock drivers	28
GTLP	30
Product selection guides	31

**Timing & Interface** 

#### TLK2208 Application Diagram



#### Applications:

- Building blocks for developing point-to-point baseband data transmission over controlled impedance media of 50  $\Omega$
- BTS backplane
- Radio card-to-controller interconnect

### HIGH-SPEED, POINT-TO-POINT 8-CHANNEL GIGABIT ETHERNET TRANSCEIVERS

#### Get datasheets at:

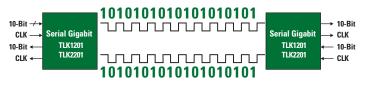
#### www.ti.com/sc/device/tlk2208

The TLK2208 is TI's third generation of gigabit Ethernet transceivers that combines high-port density and ultra-low power in a small-form-factor footprint. The device provides for high-speed, full-duplex, point-to-point data transmissions based on the IEEE 802.3z 1000-Mbps Ethernet specification.

#### Key Features:

- New: eight-channel gigabit Ethernet transceiver
- Selectable 8-B/10-B encoding/decoding
- Two data sampling modes (multiplex mode or nibble mode) enable a reduced pin count for interfacing MAC, ASIC, or FPGA
- Each channel operates from 1.0 1.3 Gbps
- Provides a maximum total aggregated data bandwidth of 8.32 Gbps over a copper or optical media interface

#### TLK1201 Block Diagram



#### Applications:

- High-port-density applications where board space and power are limited
- Point-to-point base station and controller backplane links (shown above)

#### GIGABIT ETHERNET- AND FIBRE CHANNEL-COMPLIANT TRANSCEIVERS TLK1201/TLK2201

Get datasheets, samples, and application reports at: www.ti.com/sc/device/partnumber

Replace partnumber in URL with tlk1201 or tlk2201

TI's TLK1201 and TLK2201 gigabit Ethernet- and fibre channelcompliant transceivers require 8-B/10-B encoded data on the parallel side. The devices can be run in either normal 10-bit mode or a reduced 5-bit mode, which clocks in data on the rising and falling clock edges (DDR mode).

#### Key Features:

- Low power consumption: <200 mW at 1.25 Gbps
- LVPECL-compatible differential I/O on high-speed interface
- Single monolithic PLL design
- Receiver differential input thresholds 200 mV (min)
- IEEE 802.3 gigabit Ethernet compliant
- 2.5-V supply voltage for lowest-power operation
- 3.3-V tolerant on LVTTL inputs
- Hot-plug protection
- Industrial temperature range from -40°C to 85°C
- Packaging: 64-pin VQFP, thermally enhanced (PowerPAD™)

#### LVDS SerDes BACKPLANE TRANSMITTER/ RECEIVER CHIPSETS

SN65LV1021, SN65LV1023, SN65LV1212, SN65LV1224

#### Get datasheet and samples at:

#### www.ti.com/sc/device/partnumber

Replace partnumber in URL with sn65lv1021, sv65lv1023, sn65lv1212, or sn65lv1224

TI's SN65LV1021/1023 transmitter and SN65LV1212/1224 receiver family of devices is designed to provide BTS backplane solutions between 100 Mbps and 660 Mbps. The chipset has a 10-bit LVTTL parallel-side input/output and a high-speed LVDS serial-side input/output.

#### Key Features:

- 100-Mbps to 400-Mbps serial LVDS data payload bandwidth at 10-MHz to 40-MHz system clock (SN65LV1021/23)
- 300-Mbps to 660-Mbps serial LVDS data payload bandwidth at 30-MHz to 66-MHz system clock (SN65LV1212/24)
- Pin-compatible superset of NSM DS92LV1021/1212, NSM DS92LV1023/1224
- Chipset (serializer/deserializer) power consumption: <250 mW (typ) (Tx) and <400 mW (typ) (Rx)
- Synchronization mode for faster lock

#### 16:1 SERIALIZER/DESERIALIZER TRANSCEIVERS WITH PRBS TESTABILITY TLK1501, TLK2501, TLK2701, TLK2711, TLK3101, TLK4015

Get datasheets, samples, EVMs, and application reports at: www.ti.com/sc/device/partnumber

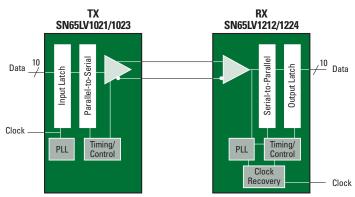
*Replace partnumber in URL with tlk1501, tlk2501, tlk2701, tlk2711, tlk3101, or tlk4015* 

TI's TLK1501, TLK2501, TLK2701, TLK2711, TLK3101, and TLK4015 provide a 16-to-1 serializer/deserializer (SerDes) function with supported data rates from 600 Mbps to 3.125 Gbps. The devices feature built-in 8-B/10-B encoding/decoding for easier design.

#### Key Features:

- Hot-plug protection
- 2.5-V power supply for low-power operation
- Programmable voltage output swing on serial output
- Interfaces to backplane, copper cables, or optical converters
- Rated for industrial temperature range
- On-chip 8-bit/10-bit encoding/decoding
- On-chip PLL provides clock synthesis from low-speed reference
- Receiver differential input thresholds 200 mV (min)
- Loss-of-signal (LOS) detection
- Packaging: 64-pin VQFP (PowerPAD<sup>™</sup>) (TLK1501, TLK2501, TLK2701, TLK3101), 80-pin Microstar Junior<sup>™</sup> BGA (GQE) (TLK2711), BGA (TLK4015)

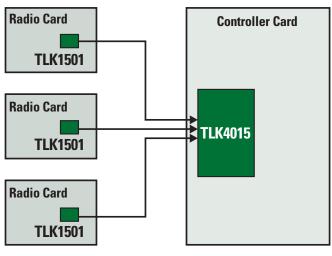




#### Applications:

- Radio-to-controller card links
- Antenna-to-receiver link
- BTS backplane

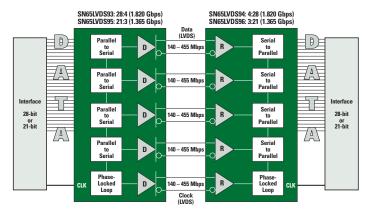




#### Applications:

- Radio-to-controller card
- Antenna-to-receiver card
- BTS backplane

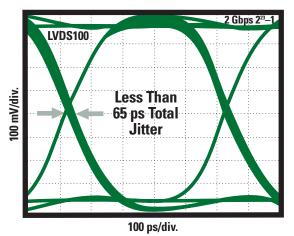
#### SN65LVDS9x Block Diagram



#### Applications:

- Base station backplane
- Radio-to-controller card links

#### Eye Pattern of LVDS100



Applications:

- CML/LVPECL-to-LVDS translator
- LVDS/CML-to-LVPECL translator
- 2×2 Crosspoint and 2:1 Mux
- 4×4 Crosspoint, 4:1 Muxs

#### 3- OR 4-CHANNEL, POINT-TO-POINT TRANSMITTER AND RECEIVER PAIR SN65LVDS96, SN65LVDS95, SN65LVDS93, SN65LVDS94

Get datasheet, samples, EVMs, and application reports at: www.ti.com/sc/device/partnumber

Replace partnumber in URL with sn65lvds96, sn65lvds95, sn65lvds93, or sn65lvds94

The SN65LVDS9x family of devices is a 3- or 4-channel (3 or 4 data channels, plus 1 clock channel) point-to-point transmitter and receiver pair which supports up to 1.365/1.820 Gbps of data throughput. It accepts 21/28 LVTTL inputs and outputs 3 or 4 LVDS lines in parallel with a clock signal.

#### Key Features:

- Operates with a single 3.3-V supply
- 5-V tolerant input
- Rising-clock-edge-triggered outputs
- Wide phase-lock input frequency range
- Low-voltage TTL (LVTTL) logic output levels
- Pin compatible with NSC:
  - DS90CR213 → SN65LVDS95 DS90CR214 → SN65LVDS96
  - DS90CR285 → SN65LVDS93 DS90CR286 → SN65LVDS94
- Industrial temperature qualified:  $T_A = -40^{\circ}C$  to  $85^{\circ}C$

#### LVPECL/CML/LVDS REPEATERS/TRANSLATORS AND CROSSPOINT SWITCHES

SN65LVDS100, SN65LVDS101, SN65CML100 SN65LVDS122, SN65LVDS125, SN65LVCP22, SN65LVCP23

Get samples, datasheets, and EVMs at: www.ti.com/sc/device/partnumber

Replace partnumber in URL with sn65lvds100, sn65lvds101, sn65cml100, sn65lvds122, sn65lvds125, sn65lvcp22, or sn65lvcp23

These high-speed repeaters/translators and crosspoint switches feature internal differential signal paths maintain for very low pulse and channel-to-channel skews.

#### Key Features:

- Total jitter < 65 ps
- Pulse skew < 50 ps
- All devices accept LVDS, CML, and LVPECL inputs
- 1:1 Translator repeaters
  - LVDS100 with LVDS output
  - LVDS101 with LVPECL output
  - CML100 with CML output
- Crosspoints
  - LVDS122 2×2 LVDS output
  - LVDS125 4×4 LVDS output
  - LVCP22 2×2 LVDS ouput
  - LVCP23 2×2 LVPECL ouput

## MULTIPOINT-LVDS FOR BACKPLANES AND CABLES

SN65MLVD080, SN65MLVD082, SN65MLVD200,

SN65MLVD201, SN65MLVD202, SN65MLVD203, SN65MLVD204, SN65MLVD205, SN65MLVD206, SN65MLVD207

Get samples, datasheets, application notes, and EVMs at: www.ti.com/sc/device/partnumber

Replace partnumber in the URL with sn65mlvd080, sn65mlvd082, sn65mlvd200, sn65mlvd201, sn65mlvd202, sn65mlvd203, sn65mlvd204, sn65mlvd205, sn65mlvd206, or sn65mlvd207

TI introduces the industry's first family of transceivers compliant with the Multipoint Low-Voltage Differential Signaling (M-LVDS) specification TIA/EIA-899. The SN65MLVD20x parts are half- and full-duplex single-channel transceivers. The SN65MLVD08x devices are 8-channel half-duplex transceivers that can operate at 125 MHz with up to 32 devices.

#### Key Features:

- Half power, 10× speed of RS-485
- Complies with M-LVDS Standard (TIA/EIA-899) also supported by alternative vendors
- Supports wired-OR configuration ideal for control lines
- Hot-plugging capability enhances reliability and robustness
- Controlled rise times for longer stub lengths

#### LOW-VOLTAGE CLOCK DRIVERS FOR CLOCK-DISTRIBUTION APPLICATIONS CDCLVP110/CDCLVD110

Get datasheets and application reports at: www.ti.com/sc/device/partnumber Replace partnumber in the URL with cdclvp110 or cdclvd110

TI's CDCLVP110 and CDCLVD110 low-voltage clock drivers support low-skew, low-jitter differential LVDS/LVPECL or HSTL (selectable) inputs (CLK0, CLK1) to 10 pairs of differential LVPECL clock outputs with minimum skew.

#### Key Features:

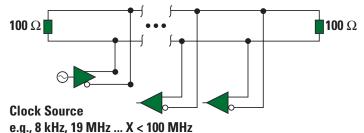
CDCLVP110

- 2.5-V or 3.3-V support
- Selectable clock input through CLK\_SEL
- Low-output skew (15 ps) max
- Cycle-to-cycle jitter less than 1 ps (rms)
- Packaging: 32-pin TQFP

#### CDCLVD110

- Accepts LVDS, LVTIL, HSTL, CML, or LVPECL signaling levels
- Signaling-rate capability up to 1.1 GHz
- Full rail-to-rail common-mode range
- Low output skew (30 ps)
- Packaging: 32-pin LQFP (VF)

#### M-LVDS for Clock Distribution Over a Backplane

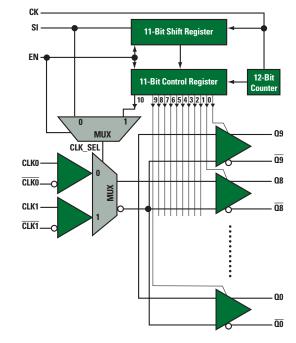


#### Applications:

#### Clock distribution

- Base station control and data bus
- Synchronization signals
- PICMG 3.0 ATCA telephony clock interface

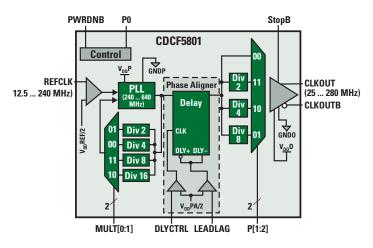
#### CDCLVxx Block Diagram



#### Applications:

- Base stations, BB card, LTU
- Cable modem headend

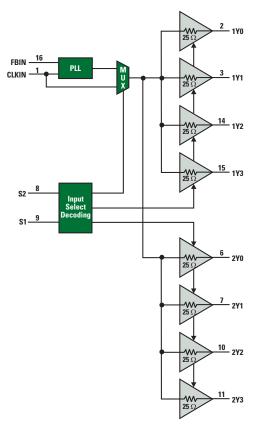
CDCF5801 Functional Diagram



#### Applications:

- Phase adjustment
- Low-jitter multiplier

#### CDCVF25084 Block Diagram



#### LOW-JITTER CLOCK MULTIPLIER WITH PROGRAMMABLE DELAY AND PHASE ALIGNMENT CDCF5801

CDCF5801

Get application notes and datasheets at: www.ti.com/sc/device/cdcf5801

The CDCF5801 provides clock multiplication from a reference clock (REFCLK) signal. It also allows delay or advance of the CLKOUT/CLKOUTB with steps of 2.6 mUI through a unique aligner.

#### Key Features:

- Low-jitter clock multiplier ×1, ×2, ×4 or ×8
  - Input frequency: 12.5 to 240 MHz
  - Output frequency: 25 to 280 MHz
- Low-jitter clock divider /2, /4 or /8
- Input frequency: 12.5 to 240 MHzOutput frequency: 25 to 280 MHz
- 2.6-mUI programmable bidirectional delay steps
- One single-ended input and one differential output pair
- Output can drive LVPECL, LVDS and LVTTL
- Spread spectrum clock tracking ability to reduce EMI
- Industrial temperature range: -40°C to 85°C

# 3.3-V X4 CLOCK MULTIPLIER WITH 8 OUTPUTS CDCVF25084

Get application notes and datasheets at: www.ti.com/sc/device/cdcvf25084

The CDCVF25084 is a high-performance, low-skew, low-jitter, phase-lock loop clock multiplier. It uses a PLL to precisely align, in both frequency and phase, the output clocks to the input clock signal including a multiplication factor of four. The CDCVF25084 operates from a nominal supply voltage of 3.3 V. The device also includes integrated series-damping resistors in the output drivers that make it ideal for driving point-to-point loads.

#### Key Features:

- Phase-locked loop-based zero-delay buffer
- Operating frequency range: 10 MHz to 200 MHz
- Low jitter (cycle-cycle)
- Distributes one clock input to two banks of four outputs
- Auto frequency detection to disable device (power-down mode)
- Consumes less than 20  $\mu\text{A}$  in power-down mode
- Packaging: 16-pin TSSOP

#### Applications:

- Telecom
- Datacom

# **General Overview**

**Signal Chain** 

#### GUNNING TRANSCEIVER LOGIC PLUS

**GTLP** Family

Get samples, datasheets, and application reports at: www.ti.com/sc/gtlp

TI provides backplane interface solutions for telecom/datacomm end equipment with the open-drain GTLP technology, which provides better signal integrity and overall system improvement over traditional logic, allowing you to drive heavily loaded backplanes.

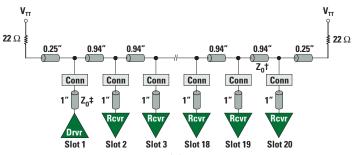
#### Key Features:

- GTLP low-output-voltage swing reduces EMI
- Reduced-input GTLP threshold provides adequate noise margin
- TI-OPC and OEC circuitry provide improved signal integrity
- I<sub>off</sub>, power-up 3-state, and BIAS V<sub>CC</sub> support live insertion
- Bi-directional interface between GTLP and LVTTL signal levels
- 5-V tolerant LVTTL I/Os allow mixed-voltage systems
- Up to 100-mA drive capability to drive heavily loaded backplanes
- Packaging: Space-saving TSSOP (DGG), TVSOP (DGV), and LFBGA (GKE/GKF) packages

#### Applications:

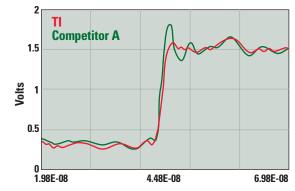
- Base stations
- Networking

Single-Bit Representation of a Multipoint Parallel Backplane



 $\dagger$  Unloaded backplane trace natural impedance ( $Z_0$ ) is 45  $\Omega$ . 45 to 60  $\Omega$  is allowed with 50  $\Omega$  being ideal.  $\ddagger$  Card stub natural impedance ( $Z_0$ ) is 60  $\Omega$ .

Signal Integrity: TI vs. Competition



#### **SERIAL GIGABIT SOLUTIONS**

Device	Function	Data Rate	Serial I/F	Parallel I/F	Power	Special Features	Price <sup>1</sup>
TLK1501	Single-ch. 16:1 SerDes	0.6–1.5 Gbps	1 CML ch.	16 LVTTL lines	200 mW	Built-in testability	Web
TLK2501	Single-ch. 16:1 SerDes	1.6–2.5 Gbps	1 CML ch.	16 LVTTL lines	300 mW	Built-in testability	Web
TLK2701	Single-ch. 16:1 SerDes	1.6–2.5 Gbps	1 CML ch.	16 LVTTL lines	300 mW	Built-in testability and K character control	Web
TLK2711	Single-ch. 16:1 SerDes	1.6–2.5 Gbps	VML	16 LVTTL lines	350 mW	MicroStar Jr.™BGA packaging	Web
TLK3101	Single-ch. 16:1 SerDes	2.5–3.125 Gbps	1 VML ch.	16 LVTTL lines	350 mW	Built-in testability	Web
TLK1201	Single-ch. 10:1 gigabit Ethernet xcvr	0.6–1.3 Gbps	1 LVPECL ch.	10 LVTTL lines	200 mW	Industrial temperature	Web
TLK2201	Single-ch.	1.0–1.6 Gbps	1 LVPECL ch.	10 LVTTL lines	200 mW	JTAG; 5-bit DDR mode	Web
TLK22011	Single-ch. 10:1 gigabit Ethernet xcvr	1.2–1.6 Gbps	1 LVPECL ch.	10 LVTTL lines	200 mW	JTAG; 5-bit DDR mode, industrial temp. qualified	Web
TLK2201JR	Single-ch. 10:1 gigabit Ethernet xcvr	1.0–1.6 Gbps	1 LVPECL ch.	10 LVTTL lines	200 mW	MicroStar Jr. 5 $\times$ 5 Land Grid Array (LGA)	Web
TLK2208	Eight-ch. of 10:1 or 8:1 gigabit Ethernet xcvr	1.0–1.3 Gbps	8 CML ch.	4/5-bit/ch (nibble DDR mode), 8/10- bit/ch (multiplex ch. mode)	1 W	JTAG, MDIO supported	Web
TLK4015	Four ch. of 16:1 xcvr	0.8–1.56 Gbps	4 CML ch.	16 LVTTL/ channel	1 W	Four-channel version of TLK1501	Web
SN65LVDS93/94	Four-ch. 28:4 TX/RX chipset	140–455 Mbps/ch.	4 LVDS	28  imes LVTTL	250 mW/ chip	Supports up to 1.82-Gbps throughput	Web
SN65LVDS95/96	Four-ch. 21:3 TX/RX chipset	140–455 Mbps/ch.	4 LVDS	28  imes LVTTL	250 mW/ chip	Supports up to 1.3-Gbps throughput	Web
SN65LV1021/ SN65LV1212	Single-ch. 10:1 TX/RX chipset	100–400 Mbps	1 LVDS	10  imes LVTTL	<400 mW/ total	Low-power solution	Web
SN65LV1023/ SN65LV1224	Single-ch. 10:1 TX/RX chipset	300-660 Mbps	1 LVDS	10  imes LVTTL	<400 mW/ total	Low-power solution	Web
SLK2501/ SLK2511	Single-ch. 4:1 multirate SONET xcvr with CDR	OC-3/12/24/48	1 LVPECL	$4 \times 622 \text{ LVDS}$	900 mW	Auto-rate detection, local and remote loop back	Web
SLK2701/ SLK2721	Single-ch. 4:1 multirate SONET xcvr with CDR	OC-3/12/24/48	PECL	$4 \times LVDS$	900 mW	FEC rate is compatible, SLK2721 is optimized for jitter tolerance	Web

<sup>1</sup>Please check www.ti.com for current pricing on these products.

#### LVDS LINE DRIVERS AND RECEIVERS

	Max Drvr/Rcvr	Мах	Max Supply	HBM ESD			Output	Pulse			
Device	t <sub>pd</sub> (ns)	Speed (Mbps)	Current (mA)	Protection (kV)	# Inputs	# Outputs	Skew (ps) <sup>2</sup>	Skew (ps) <sup>2</sup>	Package Options	Comments	Price <sup>1</sup>
SN65LVDS1	3.1	630	8	15	1 LVTTL	1 LVDS	-	300 typ	5-pin SOT-23, 8-pin SOIC	Single driver	0.66
SN65LVDS2	3.6	400	7	15	1 LVDS	1 LVTTL	-	600 max	5-pin SOT-23, 8-pin SOIC	Single receiver	0.66
SN65LVDS22	6	400	20	12	2 LVDS	2 LVDS	-	200 typ	16-pin SOIC 16-pin TSSOP	2:2 MUX (crosspoint)	3.01
SN65LVDS31	2.5	400	35	8	4 LVTTL	4 LVDS	300 max	300 max	16-pin SOIC 16-pin TSSOP	Quad driver	1.85
SN65LVDS32 <sup>3</sup>	3	400	18	8	4 LVDS	4 LVTTL	300 max	400 max	16-pin SOIC 16-pin TSSOP	Quad receiver	1.85
SN65LVDS33 <sup>3</sup>	6	400	23	15	4 LVDS	4 LVTTL	150 typ	200 typ	16-pin SOIC, 16-pin TSSOP	Quad receiver	2.22
SN65LVDS047	2.8	400	26	8	4 LVTTL	4 LVDS	300 max	300 max	16-pin SOIC, 16-pin TSSOP	Quad driver	1.83
SN65LVDS048A	3.7	400	15	10	4 LVDS	4 LVTTL	500 max	450 max	16-pin SOIC, 16-pin TSSOP	Quad receiver	1.83
SN65LVDS386 <sup>3</sup>	4	300	70	4	16 LVDS	16 LVTTL	400 max	600 max	64-pin TSSOP	16-ch. receiver	5.55
SN65LVDS387	2.9	630	95	15	16 LVTTL	16 LVDS	150 max	500 max	64-pin TSSOP	16-ch. receiver	5.55
SN75LVDS388A <sup>3</sup>	4	300	40	4	8 LVDS	8 LVTTL	400 max	600 max	38-pin TSSOP	Octal receiver	3.25
SN65LVDS389	2.9	300	70	4	8 LVTTL	8 LVDS	150 max	500 max	38-pin TSSOP	Octal driver	3.25

 $^1Suggested$  resale price in U.S. dollars in quantities of 1,000.  $^2R_L=100~\Omega,~C_L=10~pF$  with max. spec.  $^3Integrated$  termination option.

#### LVDS/LVPECL/CML REPEATERS/TRANSLATORS AND CROSSPOINTS

Device	Max Drvr/Rcvr t <sub>pd</sub> (ns)	Max Speed (Mbps)	Max Supply Current (mA)	HBM ESD Protection (kV)	# Inputs	# Outputs	Output Skew (ps)	Pulse Skew (ps)	Packaging	Comments	Price <sup>1</sup>
SN65LVDS100	0.9	2000	90	5	1 LVDS/CML/LVPECL	1 LVDS	-	50	8-pin SOIC, VSSOP	Translator/Repeater	2.52
SN65LVDS101	0.9	2000	90	5	1 LVDS/CML/LVPECL	1 LVPECL	-	50	8-pin SOIC, VSSOP	Translator/Repeater	2.52
SN65CML100	0.8	1500	30	5	1 LVDS/CML/LVPECL	1 CML	-	50	8-pin SOIC, VSSOP	Translator/Repeater	2.52
SN65LVDS122	0.9	1500	100	4	2 LVDS/CML/LVPECL	2 LVDS	40	50	16-pin SOIC, TSSOP	2×2 Crosspoint	4.75
SN65LVCP22	0.8	1000	85	8	2 LVDS/CML/LVPECL	2 LVDS	20	20	16-pin SOIC, TSSOP	2×2 Crosspoint	3.89
SN65LVCP23	1	2000	65	5	2 LVDS/CML/LVPECL	2 LVPECL	20	20	16-pin SOIC, TSSOP	2×2 Crosspoint	4.95
SN65LVDS125	1	1500	100	8	4 LVDS/CML/LVPECL	4 LVDS	50	50	38-pin TSSOP	4×4 Crosspoint	8.70

<sup>1</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

#### **GTLP TRANSCEIVERS**

Device	Description	Status	Price <sup>1</sup>
SN74GTLP1394	2-bit LVTTL-to-GTLP adjustable-edge-rate bus Xcvr w/ split LVTTL port, feedback path, and selectable polarity	Active	2.73
SN74GTLP1395	Two 1-bit LVTTL/GTLP adjustable-edge-rate bus Xcvrs w/ split LVTTL port, feedback path, and selectable polarity	Active	1.75
SN74GTLP2033	8-bit LVTTL-GTLP adjustable-edge-rate registered transceiver with split LVTTL port and feedback path	Active	3.85
SN74GTLP2034	8-bit LVTTL-GTLP adjustable-edge-rate registered transceiver with split LVTTL port and feedback path	Active	3.85
SN74GTLP21395	Two 1-bit LVTTL/GTLP adjustable-edge-rate bus Xcvrs with split LVTTL port, feedback path, and selectable polarity	Active	1.75
SN74GTLP22033	8-bit LVTTL-GTLP adjustable-edge-rate registered transceiver with split LVTTL port and feedback path	Active	3.85
SN74GTLP22034	8-Bit LVTTL-GTLP adjustable-edge-rate registered transceiver with split LVTTL port and feedback path	Active	3.85
SN74GTLP817	GTLP-to-LVTTL 1-to-6 fanout driver	Active	2.45
SN74GTLPH1612	18-bit LVTTL-to-GTLP adjustable-edge-rate universal bus transceiver	Active	5.95
SN74GTLPH1616	17-bit LVTTL-to-GTLP adjustable-edge-rate universal bus transceiver with buffered clock outputs	Active	5.95
SN74GTLPH1645	16-bit LVTTL-to-GTLP adjustable-edge-rate bus transceiver	Active	2.45
SN74GTLPH1655	16-bit LVTTL-to-GTLP adjustable-edge-rate universal bus transceiver	Active	5.95
SN74GTLPH16612	18-bit LVTTL-to-GTLP universal bus transceiver	Active	4.62
SN74GTLPH16912	18-bit LVTTL-to-GTLP universal bus transceiver	Active	4.90
SN74GTLPH16916	17-bit LVTTL-to-GTLP universal bus transceiver with buffered clock outputs	Active	4.90
SN74GTLPH16945	16-bit LVTTL-to-GTLP bus transceiver	Active	2.10
SN74GTLPH306	8-bit LVTTL-to-GTLP bus transceiver	Active	3.08
SN74GTLPH3245	32-bit LVTTL-to-GTLP adjustable-edge-rate bus transceiver	Active	3.71
SN74GTLPH32912	36-bit LVTTL-to-GTLP universal bus transceiver	Preview	Call
SN74GTLPH32916	34-bit LVTTL-to-GTLP universal bus transceiver with buffered clock outputs	Active	7.00
SN74GTLPH32945	32-bit LVTTL-to-GTLP bus transceiver	Active	3.15
Suggested resale price i	n U.S. dollars in quantities of 1,000.		

Suggested resale price in U.S. dollars in quantities of 1,000.

#### **M-LVDS TRANSCEIVERS**

		No.	No.			RX	Part-to- Part	Signal- ing	Tx t <sub>pd</sub>	Rx t <sub>pd</sub>	Icc	ESD	Supply		
Device Name	Description	of Tx	of Rx	Input Signal	Output Signal	Type 1 or 2	Skew Max (ps)	Rate (Mbps)	Typ (ns)	Typ (ns)	Max (mA)	HBM (kV)	Voltage (V)	Pin/ Package	Price <sup>1</sup>
SN65MLVD200	Half-duplex M-LVDS xcvr	1	1	LVTTL, M-LVDS	LVTTL, M-LVDS	1	2500	100	2.3	4.6	26	3	3.3	8-pin SOP	1.84
SN65MLVD201	Half-duplex M-LVDS xcvr	1	1	LVTTL, M-LVDS	LVTTL, M-LVDS	1	1000	200	1.5	4.0	24	3	3.3	8-pin SOP	2.10
SN65MLVD202	Full-duplex M-LVDS xcvr	1	1	LVTTL, M-LVDS	LVTTL, M-LVDS	1	2500	100	2.3	4.6	26	3	3.3	14-pin SOP	1.84
SN65MLVD203	Full-duplex M-LVDS xcvr	1	1	LVTTL, M-LVDS	LVTTL, M-LVDS	1	1000	200	1.5	4.0	24	3	3.3	14-pin SOP	2.10
SN65MLVD204	Half-duplex M-LVDS xcvr	1	1	LVTTL, M-LVDS	LVTTL, M-LVDS	1	2500	100	2.3	4.6	26	3	3.3	8-pin SOP	1.84
SN65MLVD205	Full-duplex M-LVDS xcvr	1	1	LVTTL, M-LVDS	LVTTL, M-LVDS	1	2500	100	2.3	4.6	26	3	3.3	14-pin SOP	1.84
SN65MLVD206	Half-duplex M-LVDS xcvr	1	1	LVTTL, M-LVDS	LVTTL, M-LVDS	2	1000	200	1.5	4.0	24	3	3.3	8-pin SOP	2.10
SN65MLVD207	Full-duplex M-LVDS xcvr	1	1	LVTTL, M-LVDS	LVTTL, M-LVDS	2	1000	200	1.5	4.0	24	3	3.3	14-pin SOP	2.10
SN65MLVD080	Half-duplex M-LVDS xcvr	8	8	LVTTL, M-LVDS	LVTTL, M-LVDS	1	600	250	1.5	4	180	8	3.3	64-pin TSSOP	4.50
SN65MLVD082	Half-duplex M-LVDS xcvr	8	8	LVTTL, M-LVDS	LVTTL, M-LVDS	2	600	250	1.5	4	180	8	3.3	64-pin TSSOP	4.50

<sup>1</sup>Suggested resale unit price in U.S. dollars in quantities of 1,000. Please check www.ti.com for current pricing on these products.

#### **CLOCK DISTRIBUTION CIRCUITS**

Device	Description	Package Options	I/O Levels (Input/Output)	Frequency (MHz)	V <sub>CC</sub> (V)	Output Skew t <sub>sk(o)</sub> max (ns)	Price <sup>1</sup>
	lock Distribution	Options	(input/output/	(19112)	(•)	(113)	THEC
CDCVF111	1:9 diff LVPECL	28-pin PLCC	LVPECL/LVPECL	0–650	3.3	0.05	Web
CDC318A	1:18 clock driver with I <sup>2</sup> C control interface	48-pin SSOP	LVTTL/LVTTL, TTL	0-100	3.3	0.05	Web
CDC341	1:8 w/ fast $t_{pd}$ fanout	20-pin SOIC	TTL/TTL	0-80	5	0.25	Web
CDC351/2351	1:10 w/ fast t <sub>pd</sub> fanout, 3-state outputs	24-pin SOIC/SSOP	LVTTL/LVTTL	0-100	3.3	0.5	Web
CDC391	1:6 clock driver with selectable polarity	16-pin SOIC	TTL/TTL	0-100	5	0.5	Web
000001	and 3-state outputs		112/112	0 100	0	0.0	*****
CDCLVD110	1:10 programmable low-voltage LVDS clock driver	32/TQFP	LVDS/LVDS	900	2.5	30 ps typ	
CDCLVP110	1:10 low-voltage LVPECL HSTL with selectable input clock driver	32/LQFP	LVPECL or HSTL/LVPECL	3.5 GHz	2.5/3.3	30 ps	
CDCV304	1:4 fanout for PCI-X and general apps.	8-pin TSSOP	LVTTL/CMOS	0–140	3.3	0.17	Web
CDCVF2310	1:10 clock driver w/ 2 banks for general- purpose applications	24-pin TSSOP	LVTTL/LVTTL	0–170 (V <sub>DD</sub> =2.3–2.7 V) 0–200 (V <sub>DD</sub> =3–3.6 V)	2.5/3.3	170 ps @ 2.5 V 100 ps @ 3.3 V	Web
CDCM1804	1:3 LVPECL clock buffer and addl. LVCMOS output and programmable divider	24/MLF	LVPECL/ LVPECL or LVCMOS	to 800 MHz for LVPECL to 200 MHz for LVCMOS	3.3	-	Web
SN65LVDS104	1:4 diff LVDS	16-pin SOIC/TSSOP		0-315	3.3	0.1	2.22
SN65LVDS105	1:5 diff LVDS	16-pin SOIC/TSSOP	LVDS/LVDS	0-315	3.3	0.1	2.22
SN65LVDS108	1:8 diff LVDS	38-pin TSSOP	LVDS/LVDS	0-311	3.3	0.3	4.55
SN65LVDS116	1:16 diff LVDS	64-pin TSSOP	LVDS/LVDS	0-311	3.3	0.3	5.97
PLL-Based Cloc	k Distribution						
CDC516/2516 <sup>2</sup>	1:16 PLL clock driver	48-pin TSSOP	LVTTL/LVTTL	25–125	3.3	0.2	Web
CDC536/2536 <sup>2</sup>	1:6 PLL clock driver w/ (3) at 1/2× or 2× output, 3-state outputs	28-pin SSOP	LVTTL/LVTTL	25–100	3.3	0.5	Web
CDC582/2582 <sup>2</sup>	1:12 LV diff PECL PLL clock driver w/ (9) at 1/2× or 2× output	52-pin TQFP	LVPECL/LVTTL	25–100	3.3	0.5	Web
CDC586/2586 <sup>2</sup>	1:12 PLL clock driver w/ (9) at 1/2 $\!\times$ or 2 $\!\times$ output, 3-state outputs	52-pin TQFP	LVTTL/LVTTL	25–100	3.3	0.5	Web
CDC5801	Clock multiplier/divider w/ programmable delay and phase alignment	24/SSOP	LVTTL/ LVPECL or LVDS or LVTTL	150–500 / 12.5–62.5	3.3		
CDC7005	High-performance clock synthesizer	64/BGA	LVTTL/LVPECL	10–650	3.3	200 ps	
CDCF5801	Multiplier/divider with programmable delay and phase alignment	24/SSOP	LVCMOS/ LVPECL or LVDS or LVTTL	12.5 to 240 25 to 280	3.3	-	Web
CDCVF2505	1:5 PLL clock driver for general purpose, SSC	8-pin TSSOP/SOIC	LVTTL/LVTTL	24–200	3.3	0.15	Web
CDCVF2508	1:8 low-power PLL clock driver with two banks, SSC	16-pin TSSOP/SOIC	LVTTL/LVTTL	10–170	2.5/3.3	0.15	Web
CDCVF25084	1:8 low-power 4´ multiplier with two banks, SSC	16-pin TSSOP	LVTTL/LVTTL	10 to 180	3.3	150	Web
CDCVF2509	1:9 low-power PLL clock driver for PC 133 and beyond application, SSC	24-pin TSSOP	LVTTL/LVTTL	50–175	3.3	0.1	Web
CDCVF2510	1:10 low-power PLL clock driver for PC 133 and beyond application, SSC	24-pin TSSOP	LVTTL/LVTTL	50–175	3.3	0.1	Web
PLL-Based Cloc	ks for Memory Applications						
CDCV850	1:10 PLL clock driver for DDR SDRAM application, SSC compatible with two-line serial interface	48-pin TSSOP	HCSL, Universal (except ECL)/SSTL-II	60–140	2.5/3.3	0.075	Web
CDCV855	1:4 (plus feedback pair) PLL differential clock driver for DDR applications, SSC	28-pin TSSOP	SSTL-II/ SSTL-II, LVTTL	60–180	2.5	0.075	Web
CDCV857B	1:10 PLL differential clock driver for DDR applications, SSC	48-pin TSSOP	SSTL-II/SSTL-II	60–200	2.5	0.075	Web

<sup>1</sup>Suggested resale price in U.S. dollars in quantities of 1,000. Please check www.ti.com for current pricing on these products. <sup>2</sup>With series output resistors.

Preview devices are listed in blue.

Notes: For more information regarding test conditions used to obtain measurements, see datasheet. Converted from V/ns datasheet value to ns value, based on 0.4- to 2-V voltage rise/fall.

#### LOGIC

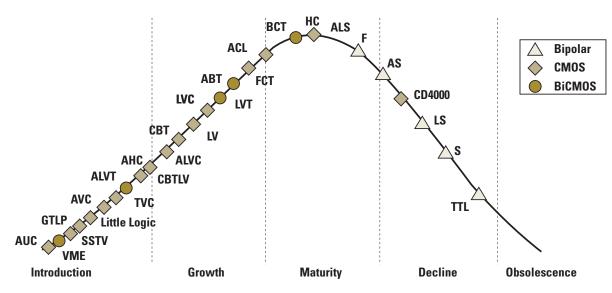
As wireless infrastructure designers look to increase data throughput, reduce power consumption, and shrink form factors, TI's logic portfolio is constantly advancing while, at the same time, the company is dedicated to providing legacy logic devices.

As the leading provider of logic, TI's latest technologies are targeted for the fast moving market of wireless infrastructure systems. Advanced CMOS families and functions, like the LVC and ALVC are optimized at 3.3-V  $V_{CC}$ . And the CBT and CBTLV families of bus switches offer designers a broad portfolio to meet diverse switching needs.

#### TO KNOW MORE 🕨

For detailed information about lo wireless infrastructure:	gic for
Buffer/driver	36
Bus switch	36
Product selection guides	37

#### Logic Product Life Cycle



## 16-BIT BUFFER/DRIVER WITH 3-STATE OUTPUTS SN74ALVC16244A/SN74LVC16244A

#### Get samples and datasheets at:

www.ti.com/sc/device/partnumber

*Replace partnumber in the URL with sn74alvc16244a or sn74lvc16244a* 

Ideal for base station and networking applications, both the LVC and ALVC families of logic technologies offer solutions for speedcritical 3.3-V system designs. The LVC family is a highperformance version with 0.8- $\mu$  CMOS process technology. With typical propagation delays of less than 2 ns, ALVC provides 24 mA of current drive and static power consumption.

#### Key Features:

- 3.6-ns max t<sub>pd</sub> at 3.3 V (ALVC)
- 5.2-ns max t<sub>pd</sub> at 3.3 V (LVC)
- I<sub>off</sub> circuitry (LVC)
- Packaging: BGA

#### ALVC PARAMETRICS

Parameter Name	SN74ALVC16244A
Voltage nodes (V)	3.3, 2.7, 2.5, 1.8
V <sub>CC</sub> range (V)	2.3 to 3.6
Input level	LVTTL
Output level	LVTTL
Output drive (mA)	-24/24
t <sub>pd</sub> max (ns)	3.6
Static current	0.04

# LOW-VOLTAGE QUADRUPLE-FET BUS SWITCH SN74CBTLV3125

Get samples and datatsheets at: www.ti.com/sc/device/sn74cbtlv3125

The CBTLV family of bus switches operate at the low-voltage 3.3-V operating node. These high-speed bus-connect devices benefit designs with greater system speed and reduced power consumption. The SN74CBTLV3125 quadruple-FET bus switch features independent line switches. Each switch is disabled when the associated output-enable (OEV) input is high.

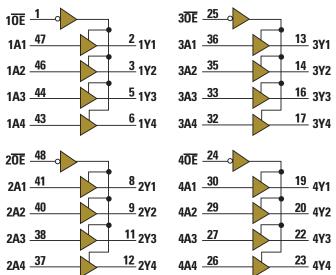
#### Key Features:

- Standard SN74CBTLV3125-type pinout
- 5- $\Omega$  switch connection between two ports
- Isolation under power-off conditions
- Latch-up performance exceeds 100 mA per JESD 78, Class II

#### Applications:

- Base stations
- Networking

SN75ALVC16244A Logic Diagram (Positive Logic)

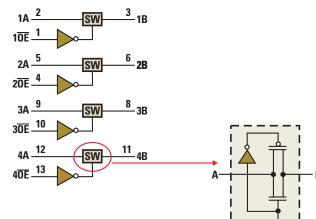


Pin numbers shown are for the DGG and DL packages.

#### Applications:

- Base stations
- Networking

#### SN74CBTLV3125 Block Diagram



(OE)

#### **CBTLV3125 PARAMETERS**

Parameter Name	SN74CBTLV3125
Voltage nodes (V)	3.3, 2.5
V <sub>CC</sub> range (V)	2.3 to 3.6
No. of bits	4
ron max (ohms)	7
t <sub>pd</sub> max (ns)	0.25

**Power Management** 

## SN74CBTLV31x BUS SWITCHES

Orderable Device	Package	Pins	Temp (°C)	Status	Pack Quantity	Price <sup>1</sup>
SN74CBTLV3125D	D	14	-40 to 85	Active	50	0.81
SN74CBTLV3125DBQR	DBQ	16	-40 to 85	Active	2500	0.81
SN74CBTLV3125DGVR	DGV	14	-40 to 85	Active	2000	0.81
SN74CBTLV3125DR	D	14	-40 to 85	Active	2500	0.81
SN74CBTLV3125NSR	NS	14	-40 to 85	Active	2000	0.88
SN74CBTLV3125PWR	PW	14	-40 to 85	Active	2000	0.81

<sup>1</sup>Suggested resale price in U.S. dollars.

## **ALVC BUFFER/DRIVERS**

Orderable Device	Package	Pins	Temp (°C)	Status	Pack Quantity	Price <sup>1</sup>
SN74ALVC16244ADGGR	DGG	48	-40 to 85	Active	2000	1.12
SN74ALVC16244ADL	DL	48	-40 to 85	Active	25	1.12
SN74ALVC16244ADLR	DL	48	-40 to 85	Active	1000	1.12
SN74ALVC16244AGQLR	GQL	56	-40 to 85	Active	1000	1.23

<sup>1</sup>Suggested resale price in U.S. dollars.

## **LVC PRODUCTS**

Orderable Device	Package	Pins	Temp (°C)	Status	Pack Quantity	Price <sup>1</sup>
SN74LVC16244ADGGR	DGG	48	-40 to 85	Active	2000	1.01
SN74LVC16244ADGVR	DGV	48	-40 to 85	Active	2000	1.01
SN74LVC16244ADL	DL	48	-40 to 85	Active	25	1.01
SN74LVC16244ADLR	DL	48	-40 to 85	Active	1000	1.01
SN74LVC16244AGQLR	GQL	56	-40 to 85	Active	1000	1.12

<sup>1</sup>Suggested resale price in U.S. dollars.

Read more about Wireless Infrastructure solutions at www.ti.com/wisolutionsguide

## **POWER MANAGEMENT PRODUCTS**

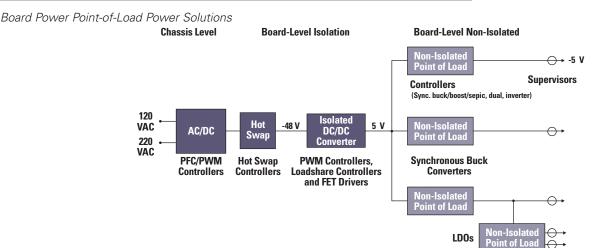
For detailed information, visit: power.ti.com

Wireless infrastructure (WI) systems require that designers consider a wide range of power management technology. From discrete devices to modular approaches, WI designers must select technology that addresses the technical challenge of the system and offers ancillary benefits in terms of ease-of-use and supply chain reliability and efficiency.

Much of TI's broad range of power management products has been targeted at wireless infrastructure applications. Based on extensive experience with power technology, TI's solutions address application challenges that designers face daily. With solutions for both portable and board power applications, TI has a comprehensive array of power management solutions. In addition, its market-proven record of expertise has made TI's power technology very easy to use for designers. A wide range of both discrete devices and isolated and non-isolated modular power technology is available.

Some of the products specific to wireless infrastructure applications include the following:

- DC/DC Controllers and Converters: These devices will generate regulated supply rails. The TPS54xxx (SWIFT™) family of converters integrates the output FETs to simplify design and the family provides output currents up to 9 A. New controllers, such as the TPS40K<sup>™</sup> series, are ideal for a broader range of input voltages and output currents.
- **Isolated Plug-In Modules:** A number of products are specifically designed for 48-V bus applications. Many devices feature multiple channels for improved integration and lower system cost.
- **Non-Isolated Plug-In Modules:** Modules specifically designed for point-of-load applications come in high-performance packaging. A broad range of voltage and current options make these devices ideal for wireless infrastructure systems.
- Hot Swap Power Managers: New TPS2490, TPS2491 and TPS2350 hot swap devices are specifically designed for the 48-V bus used in infrastructure systems. These new devices add to the family of TPS239x hot swap devices.
- **MOSFET Gate Drivers:** A powerful family of gate driver ICs, featuring a combined bipolar and MOSFET manufacturing process, delivering fast switching transitions and high current output capability
- PWM Controllers and Special Functions: The industry's largest selection of controllers and an extensive selection of support ICs facilitate the efficient design of discrete power supplies.
- Linear Regulators: For the lowest-cost power solution, a broad range of LDOs support currents ranging from 10 mA to 7 A.



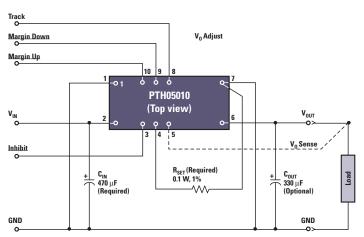
### TO KNOW MORE >

For detailed information about power management ICs for wireless infrastructure:

DC/DC converters	39
Controllers	40
MOSFET driver	43
LoadShare controller	43
LDOs	44
Product selection guides	45

Logic

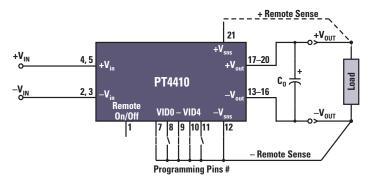




#### Applications:

- Wireless infrastructure
- Telecom
- Networking
- Servers

#### PT4410 Block Diagram



#### Applications:

- Wireless infrastructure
- Telecom
- Networking

#### POINT-OF-LOAD POWER MODULES OFFER AUTO-TRACK<sup>™</sup> SEQUENCING PTH Series of Point-of-Load Modules

#### Get samples and datasheets at:

www.ti.com/sc/device/part number Replace partnumber in the URL with pthxx000, pthxx050, pthxx060, pthxx010, pthxx0020, pthxx030 where xx = input voltage = 03, 05, or 12

The PTHxx series of plug-in power modules will support step-down DC/DC conversion from a 3.3 V, 5 V or 12 V input with adjustable output voltages from 0.8 V to 5.5 V at output currents up to 30 A. The power modules incorporate an innovative new Auto-Track sequencing technology, which allows multiple modules to be powered up and down in sequence without external circuitry.

#### Key Features:

- Auto-Track sequencing
- Margin-up/down controls
- Pre-bias startup capability
- Output current up to 30 A
- Efficiencies up to 96%
- Point-of-Load Alliance (POLA) compatible
- Packaging: Low-profile DIP module

### 75-W/100-W CONVERTERS OFFER 90% EFFICIENCY PT4410

Get samples and datasheets at: www.ti.com/sc/device/pt4410

The PT4410 series of power modules are single-output isolated DC/DC converters housed in a compact 21-pin low-profile (12-mm) package. These modules are rated up to 75 W with load currents as high as 30 A. The output voltage is set within a predefined range via a 5-bit input code and is adjustable.

#### Key Features:

- 90% efficiency
- Output power: 75 W or 100 W
- 36-V to 75-V input
- 5-bit programmable output voltage
- 1500-V DC isolation
- On/off control
- Over-current protection
- Differential remote sense
- Output over-voltage protection
- Over-temperature shutdown
- Under-voltage lockout
- Space-saving solderable copper case
- Packaging: Low profile, 12 mm

**General Overview** 

#### TRIPLE-OUTPUT MODULES FEATURE 50% SMALLER FOOTPRINT PLUS SEQUENCING PT4820/PT4850

#### Get samples and datasheets at: www.ti.com/sc/device/partnumber

Replace partnumber in the URL with pt4820 or pt4850

The PT4820 and PT4850 Excalibur™ power modules are a series of isolated triple-output DC/DC converters that operate from a standard (-48 V) central office supply. These modules are rated for a combined output of up to 12 A or 25 A and are designed for powering mixed-logic applications. Output voltage options include a low-voltage output for a DSP or ASIC core and two additional supply voltages for the I/O and other functions.

#### Key Features:

- Three independently regulated outputs
- Internal power-up and power-down sequencing
- Output power: 35 W or 75 W
- Input voltage range: 36 V to 75 V
- 1500-V DC isolation
- Dual logic-on/off control
- Short-circuit protection (all outputs)
- Over-temperature shutdown

## -48 V, 8-PIN, HOT SWAP CONTROLLERS

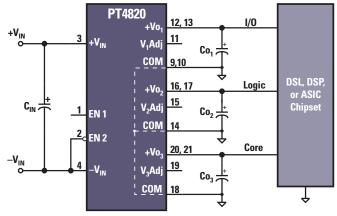
Get samples and datasheets at: www.ti.com/sc/device/partnumber Replace partnumber in the URL with tps2390 or tps2391

The TPS2390 and TPS2391 Hot Swap power managers are optimized for use in nominal -48-V systems. Designed for supply voltage ranges up to -80 V, they are rated to withstand spikes to -100 V. In conjunction with an external N-channel FET and sense resistor, these controllers can be used to enable the live insertion of plug-in cards and modules in powered systems.

#### Key Features:

- Wide input supply range: -36 V to -80 V
- Transient rating to -100 V
- Programmable current limit and current slew rate
- Enable input (EN)
- Fault timer to eliminate nuisance trips
- Open-drain fault output
- Requires few external components
- Packaging: 8-pin MSOP

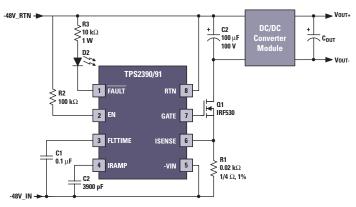
#### PT4820/50 Block Diagram



#### Applications:

- Wireless infrastructure
- Telecom
- Networking

#### TPS2390/91 Block Diagram

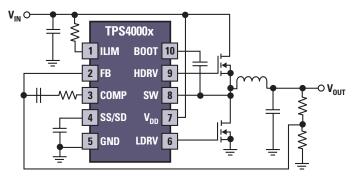


#### Applications:

- On-card hot swap
- -48-V distributed power systems

Device	Auto-Retry	Output
TPS2350	Yes	PG
TPS2390	No	Fault
TPS2391	Yes	Fault
TPS2392	No	PG/Fault
TPS2393	Yes	PG/Fault
TPS2398	No	PG
TPS2399	Yes	PG
TPS2490	No	PG
TPS2491	Yes	PG

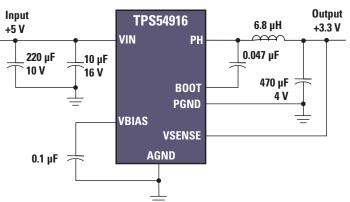
TPS4000x Block Diagram



#### Applications:

- Wireless infrastructure
- Networking equipment
- Telecom equipment
- Base stations
- DSP power

#### TPS54916 Block Diagram



Part Number	I <sub>OUT</sub> (A)	V <sub>IN</sub> (V)	V <sub>OUT</sub> (V)	Price <sup>1</sup>
TPS54910	9	3–4	Adj. to 0.9 V	5.20
TPS54810	8	4–6	Adj to 0.9 V	4.90
TPS5461x	6	3–6	0.9, 1.2, 1.5, 1.8,	4.65
			2.5, 3.3 V adj.	
TPS5431x*	3	3–6	0.9, 1.2, 1.5, 1.8	3.45
			2.5, 3.3 V adj.	

\*20-pin HTSSOP package

<sup>1</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

#### HIGH-EFFICIENCY SYNCHRONOUS BUCK DC/DC CONTROLLERS TPS4000x

## Get samples and datasheets at: power.ti.com

The TPS4000x are controllers for low-voltage, non-isolated synchronous buck regulators and drive N-channel power MOSFETs. They control the delays from main switch-off to rectifier turn-on and from rectifier turn-off to main switch turn-on, minimizing diode losses (both conduction and recovery) in the synchronous rectifier with TI's proprietary Predictive Gate Drive™ technology.

#### Key Features:

- Input voltage range: 2.25 V to 5.5 V
- $\bullet\,$  Output voltage as low as 0.7 V
- 1% internal 0.7-V reference
- Predictive Gate Drive N-channel MOSFET drivers for higher efficiency
- Externally adjustable soft-start and overcurrent limit
- Fixed-frequency, 300-kHz or 600-kHz voltage-mode control
- Packaging: 10-lead MSOP PowerPAD™ for higher performance

### SYNCHRONOUS BUCK DC/DC CONVERTERS WITH INTEGRATED MOSFETS TPS54916

For datasheets, samples, app notes, EVMs, and software, go to: power.ti.com/swift

Key Features:

- Input voltage range: 3.0 V to 6.0 V  $\,$
- Internal MOSFET switches for high efficiency at full load output current
- Adjustable output voltage range down to 0.9 V with 1.0% accuracy
- Wide PWM frequency: Fixed 350 kHz, 550 kHz, or adjustable 280 kHz to 700 kHz
- Load protected by peak current limit and thermal shutdown
- PowerGood, enable, and slow-start
- Reduces board area and component count
- Packaging: 28-pin HTSSOP

#### Applications:

- Low-voltage, high-density distributed power
- Point-of-load regulation for high-performance DSPs, FPGAs, ASICs, and microprocessors
- Broadband, networking, and optical communications infrastructure

#### TRACKING SWITCHER WITH INTEGRATED FETS FOR SEQUENCING TPS54680

Get datasheets, EVMs, samples, application notes, and software tools at:

#### www.ti.com/sc/device/tps54680

System designers must consider the timing and voltage differences between core and I/O power supplies (i.e., power supply sequencing) during power up and power down. The TPS54680 solution easily accomplishes simultaneous power-up and powerdown without the need of additional complex sequencing circuitry.

#### Key Features:

- Power-up/down tracking
- Input voltage range: 3.0 V to 6.0 V
- Internal 30-m $\Omega,$  12-A peak MOSFET switches for high efficiency at 6-A continuous output
- Switching frequency fixed at 350 kHz or adjustable from 280 kHz to 700 kHz
- PowerGood and enable functions
- Load protected by peak current limit and thermal shutdown
- Packaging: 28-pin HTSSOP PowerPAD™

#### 95% EFFICIENT, 600-mA, STEP-DOWN CONVERTERS TPS6200x

#### Get datasheets and samples at:

www.ti.com/sc/device/partnumber

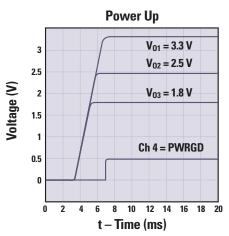
Replace partnumber in URL with tps62000, tps62001, tps62002, tps62003, tps62004, tps62005, tps62006, tps62007, or tps62008

The TPS6200x high-efficiency, synchronous step-down converters are ideal for high-efficiency power conversion in sub-systems with input voltages between 2.0 V and 5.5 V.

#### Key Features:

- 2.0-V to 6.0-V input voltage range
- Adjustable-output voltage range from 0.8 V to  $V_{\rm I}$
- Fixed-output voltage options available
- Up to 600-mA output current
- Synchronizable to external clock signal up to 1 MHz
- Highest efficiency over wide-load current range due to PFM power-save mode
- 50-μA quiescent current (typ)
- Packaging: 3 × 5 mm<sup>2</sup> MSOP-10

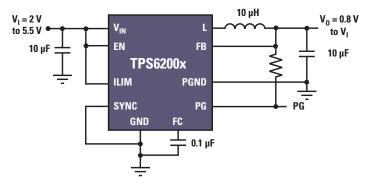
#### Sequential Startup Waveform



#### Applications:

- DSPs, FPGAs, ASICs, and microprocessors that require simultaneous start up
- Broadband, datacom, and optical communications infrastructure
- Precision point-of-load regulation

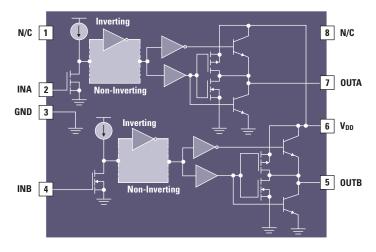
#### TPS6200x Application Diagram



#### Applications:

- DSP
- µC processor core
- System voltage supply

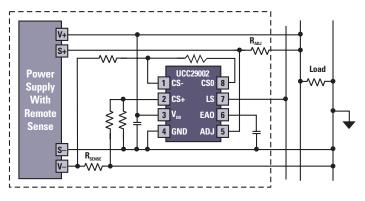
#### UCC27323 Block Diagram



#### Applications:

- Switch-mode power supplies:
- Off-line power supplies
- DC/DC converters
- Board mount power supplies

UCC29002 Typical Low-Side Current-Sensing Application



#### System Configurations:

- Modules with remote sense capability
- Modules with adjust input
- Modules with both remote sense and adjust input
- In conjunction with the internal feedback E/A of OEM power supply units

#### Applications:

- Paralleled solution for DC/DC distribution
- Redundant power supplies
- SMPS for (web) servers
- Server, workstation, and telecom systems

## DUAL, 4-AMP, MOSFET GATE DRIVER

Get samples and datasheets at: www.ti.com/sc/device/ucc27323

The UCC27323/4/5 family of high-speed dual-MOSFET drivers can deliver large peak currents into capacitive loads, typical of a power MOSFET gate. Three standard logic options are offered – dual-inverting, dual-noninverting, and one inverting and one non-inverting driver.

#### Key Features:

- High current drive capability of ±4 A at the Miller Plateau region
- Industry-standard pin-out
- Efficient constant-current sourcing using a unique bipolar and CMOS output stage
- TTL-/CMOS-compatible inputs independent of supply voltage
- 4-V to 15-V supply voltage
- Packaging: Thermally enhanced MSOP PowerPAD  $^{\mbox{\scriptsize M}}$  with 4.7 C/W  $\theta_{ic}$

#### LOADSHARE CONTROLLER FOR PARALLEL POWER SUPPLIES UCC29002

Get samples and datasheets at: www.ti.com/sc/device/ucc29002

The UCC29002 is an advanced, high-performance, low-cost LoadShare controller that provides all necessary functions to parallel multiple independent power supplies or DC-to-DC modules. Targeted for high-reliability applications in telecom distributedpower systems, the controller is suitable for N+1 redundant systems or high-current applications where off-the-shelf power supplies need to be paralleled.

#### Key Features:

- High accuracy, better than 1% current share error at full load
- High-side or low-side (GND reference) current-sense capability
- Ultra-low offset current-sense amplifier
- Single-wire LoadShare bus
- Full scale adjustability
- Intel  $^{\ensuremath{\mathbb{R}}}$  SSI LoadShare specification compliant
- Disconnect from LoadShare bus at stand-by
- LoadShare bus protection against shorts to GND or to the supply rail
- Packaging: 8-pin MSOP minimizes space
- Lead-free assembly

**General Overview** 

Logic

## LOW-INPUT-VOLTAGE, OUTPUT-CAP-FREE, 1-A LDOS FOR SIMPLE, HIGHLY EFFICIENT REGULATION

TPS725xx/TPS726xx

Get samples, datasheets, and EVMs at: power.ti.com

The TPS725xx/726xx families of Low-Dropout Regulators (LDOs) help you achieve as high as 83% efficiency with the low-input-voltage feature, rivaling a switch-mode solution. These devices offer simplicity, minimized component count, and low-noise performance in post-regulation applications, as shown in the diagram.

#### Key Features:

- Supports input voltages as low as 1.8 V (and up to 5.5 V), allowing up to 83% efficiency
- No output capacitor required for stability
- 1-A LDO with integrated SVS (50-ms delay), TPS725xx
- 1-A LDO with integrated SVS (200-ms delay), TPS726xx
- 1.5-/1.6-/1.8-/2.5-V fixed-output, and adjustable-output versions available
- Dropout voltage typically 170 mV at 1 A
- Less than 1- $\mu$ A quiescent current in shutdown mode
- Packaging: SOT-223-5, DDPAK

# ULTRA-LOW-NOISE, HIGH-PSRR, FAST-RF LDO IN SOT-23

#### TPS791xx/TPS792xx/TPS793xx/TPS794xx/TPS795xx/TPS796xx/ TPS786xx

Get samples, datasheets, and EVMs at: power.ti.com

The TPS79xxx family of Low-Dropout Regulators (LDOs) features extremely high PSRR and ultra-low-noise performance to support noise-sensitive applications such as powering RF amplifiers.

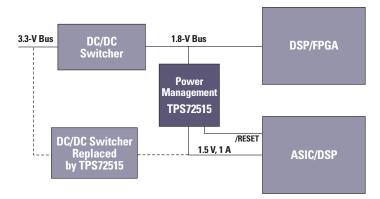
#### Key Features:

- Output current: 100 mA to 1.5 A (see table at right)
- Input voltage: 2.7 V to 5.5 V
- Output capacitor: 1.0-µF or 2.2-µF ceramic
- High PSRR: 70 dB at 10 kHz
- Ultra-low noise: 15 μVRMS (TPS791xx)
- Fast start time: 50 μs (TPS792xx)
- Dropout voltage: 38 mV at 100 mA (TPS791xx)
- Packaging: SOT-23-5, MSOP-8, SOT-223-5, DDPAK

#### Applications:

- RF
- VCOs
- DSP/FPGA/ASIC/microprocessor supplies

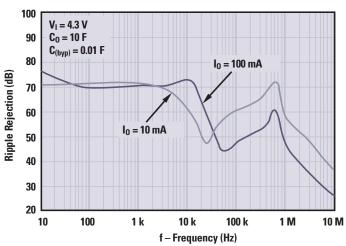
#### TPS725xx Application Diagram



#### Applications:

- Post-regulation of switch-mode supplies
- Powering core voltages of DSPs, FPGAs, ASICs, and microprocessors

#### TPS791xx PSRR Performance



Device <sup>1</sup>	l <sub>o</sub> (mA)	V <sub>o</sub> (V)	Peak Current (mA)
TPS791xx	100	1.8/3.3/4.7/adj.	285
TPS792xx	100	2.5/2.8/3.0/adj.	285
TPS793xx	200	1.8/2.5/2.8/2.85/	285
		3.0/3.3/4.75/adj.	
TPS794xx	250	1.8/2.5/2.8/3.0/3.3/adj.	700
TPS795xx	500	1.6/1.8/2.5/3.0/3.3/adj.	2400
TPS796xx	1000	1.8/2.5/2.8/3.0/3.3/adj.	2400
TPS786xx	1500	1.8/2.5/2.8/3.0/3.3/adj.	2400

<sup>1</sup>xx represents the 2 digits of output voltage.

## DC/DC CONVERTERS (INTEGRATED SWITCH)

										Features							Packaging										
Device	I <sub>ОUТ</sub> (mA)	Switch Current Limit (max) (mA)	V <sub>IN</sub> (V)	V <sub>OUT</sub> Adj (V)	V <sub>OUT</sub> Fix (V)	Efficiency (%)	Switching Frequency (max) (kHz)	Quiescent Current (typ) (mA)	Shutdown Current (typ) (µA)	Shutdown	LDO (mA)	Low Battery	Power Good	Power Sequencing	Dual Input Bus (3.3, 2.5 V)	Undervoltage Lockout	DDR Memory	DSDS	Current Limit	Thermal Limit	S0T-23	MSOP	QFN	TSSOP	SOIC	EVM	Price <sup>2</sup>
Low Power	r Step Down	(Buck) (	Converters	— up to 1.2	2 A																						
TPS62200	300	670	2.5 to 6.0	0.7 to 6.0	_	97	1000	0.015	0.1	V						V			V	V	6					V	1.29
TPS62201	300	670	2.5 to 6.0	_	1.5	97	1000	0.015	0.1	V						<b>v</b>			V	V	6						1.29
TPS62202	300	670	2.5 to 6.0	_	1.8	97	1000	0.015	0.1	V						~			V	V	6						1.29
TPS62203	300	670	2.5 to 6.0	_	3.3	97	1000	0.015	0.1	V						~			V	V	6					V	1.29
TPS62204	300	670	2.5 to 6.0	_	1.6	97	1000	0.015	0.1	V						~			V	V	6						1.29
TPS62205	300	670	2.5 to 6.0	_	2.5	97	1000	0.015	0.1	V						V			V	V	6						1.29
TPS62206	300	670	2.5 to 6.0	_	2.6	97	1000	0.015	0.1	V						V			V	V	6						1.29
TPS62000	600	1600	2.0 to 5.5	0.8 to 5.0	_	95	1000	0.05	0.1	V		V	V			V			V			10				~	1.49
TPS62001	600	1600	2.0 to 5.5		0.9	95	1000	0.05	0.1	v		V	v			~			~			10					1.49
TPS62002	600	1600	2.0 to 5.5	_	1.0	95	1000	0.05	0.1	V		V	v			~			v			10					1.49
TPS62002	600	1600	2.0 to 5.5	_	1.0	95	1000	0.05	0.1	v		V	v			v			v			10					1.49
TPS62004	600	1600	2.0 to 5.5	_	1.5	95	1000	0.05	0.1	V		V	v			v			v			10					1.49
TPS62004	600	1600	2.0 to 5.5	_	1.5	95 95	1000	0.05	0.1	v		V	v			v			v			10				~	1.49
TPS62005	600	1600		_	2.5	95 95	1000	0.05	0.1	V		V	v	-		v			v			10				~	1.49
			2.0 to 5.5																								
TPS62007	600	1600	2.0 to 5.5	-	3.3	95	1000	0.05	0.1	V		~ ~	~	_	_	V			2 2			10					1.49
TPS62008	600	1600	2.0 to 5.5	_	1.9	95	1000	0.05	0.1	4		V	V			V			V			10					1.49
	tep Down (B			up to 9 A	_		_		_																		
TPS54310	3000	6500	3.0 to 6.0	0.9 to 4.5	-	90	700	6.2	1000	~		_	V		_	_			~					20		V	3.45
TPS54311	3000	6500	3.0 to 6.0	—	0.9	90	700	6.2	1000	V			V						V	V		1		20			3.45
TPS54312	3000	6500	3.0 to 6.0	—	1.2	90	700	6.2	1000	V			~			_			V	V				20			3.45
TPS54313	3000	6500	3.0 to 6.0	—	1.5	90	700	6.2	1000	V			V						V	V				20			3.45
TPS54314	3000	6500	3.0 to 6.0	—	1.8	90	700	6.2	1000	~			V						V	V				20		~	3.45
TPS54315	3000	6500	3.0 to 6.0	—	2.5	90	700	6.2	1000	1			V						V	V				20			3.45
TPS54316	3000	6500	3.0 to 6.0	—	3.3	90	700	6.2	1000	•			V						V	V				20			3.45
TPS54372	3000	6500	3.0 to 6.0	0.2 to 4.5	—	90	700	6.2	1000	V							~		V	V				20		1	3.45
TPS54610	6000	10000	3.0 to 6.0	0.9 to 4.5	_	90	700	11	1000	V			V						V	V				28		~	4.65
TPS54611	6000	10000	3.0 to 6.0	_	0.9	90	700	11	1000	V			V						V	V				28			4.65
TPS54612	6000	10000	3.0 to 6.0	_	1.2	90	700	11	1000	V			V						V	V				28			4.65
TPS54613	6000	10000	3.0 to 6.0	_	1.5	90	700	11	1000	V			V						V	V				28			4.65
TPS54614	6000	10000	3.0 to 6.0	_	1.8	90	700	11	1000	V			V						v	V				28		V	4.65
TPS54615	6000	10000	3.0 to 6.0	_	2.5	90	700	11	1000	V			V						~	V				28			4.65
TPS54616	6000	10000	3.0 to 6.0	_	3.3	90	700	11	1000	V			V						V	V				28			4.65
TPS54672	6000	10000	3.0 to 6.0	0.2 to 4.5		90	700	11	1000	V							~		V	V				28		V	4.65
TPS54673	6000	10000	3.0 to 6.0	0.9 to 4.5	_	90	700	11	1000	v			V				-	~	v	V				28			4.65
TPS54680	6000	10000	3.0 to 6.0	0.9 to 4.5	_	90	700	11	1000	V			V	~					~	V				28			4.65
TPS54810	8000	11000	4.0 to 6.0	0.9 to 4.5	_	85	700	11	1000	V			V						v	V				28		~	4.90
TPS54872	8000	11000	4.0 to 6.0	0.3 to 4.5	_	85	700	11	1000	V			•				~		v	v				28		v	4.90
TPS54873	8000	11000	4.0 to 0.0	0.2 to 4.5	_	85	700	11	1000	V			V				•	~	v	v				28		*	4.90
TPS54880	8000	11000	4.0 to 0.0	0.9 to 4.5		85	700	11	1000	V			V	1					~	~				20			4.30 4.90
TPS54910	9000	15000	3.0 to 4.0	0.9 to 2.5	_	90	700	11	1000	v			v						v	v				28		V	5.20
TPS54910 TPS54972	9000	15000	3.0 to 4.0	0.9 to 2.5 0.2 to 2.5		90	700	11	1000	v			~						v	V				28		v	5.20
TPS54972 TPS54973	9000	15000		0.2 to 2.5 0.9 to 2.5	_	90 90			1000	v			v					~	v	v				28		v	5.20 5.20
			3.0 to 4.0		-	90 90	700	11					V					•									
TPS54974	9000	15000	2.2 to 4.0	0.2 to 2.5	_		700	11	1000	<b>V</b>					~				V	V				28		~	5.20
TPS54980	9000	15000	3.0 to 4.0	0.9 to 2.5	—	90	700	11	1000	1			1	V					1	1				28			5.20

<sup>1</sup>Disabled sinking during start-up.

<sup>2</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

## **PLUG-IN POWER SOLUTIONS**

Device <sup>1</sup>	Input Bus Voltage (V)	Pout or l <sub>OUT</sub>	lsolated Outputs	V <sub>0</sub> Range (V)	V <sub>0</sub> Adjustable	Price <sup>2</sup>
Non-Isolated Single Positi	ve Output					
PTH03010/20/30/50/60	3.3	15 A, 22 A, 30 A, 6 A, 10 A	No	0.8 to 2.5	Yes	14.00, 18.13, 24.63, 9.10, 11.20
PTH05010/20/30/50/60	5	15 A, 22 A, 30 A, 6 A, 10 A	No	0.8 to 3.6	Yes	14.00, 18.13, 24.63, 9.10, 11.20
PTH12010/20/30/50/60	12	12 A, 18 A, 26 A, 6 A, 8 A	No	1.2 to 5.5	Yes	14.00, 18.13, 24.63, 9.10, 11.20

<sup>1</sup>See **power.ti.com** for a complete product offering.

<sup>2</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

New devices are listed in red.

New devices are listed in red.

General Overview

Read more about Wireless Infrastructure solutions at www.ti.com/wisolutionsguide

## LOW DROPOUT REGULATORS (LDOs)

					Output Options				Ň					Pac	kage	s							
Device	I <sub>0</sub> (mA)	V <sub>D0</sub> @ I <sub>0</sub> (mV)	Ι <sub>q</sub> @ Ι <sub>Ο</sub> (μΑ)	Negative Out	Voltage (V)	Adj.	Min V <sub>IN</sub>	Max V <sub>IN</sub>	Accuracy	(%)	SC70	S0T23	MSOP	S08	S0T223	PWP	T0263	T0220	PW	<b>XVADO</b> Features <sup>1</sup>	Co <sup>2</sup>	Comments	Price <sup>3</sup>
TPS797xx	10	105	1.2	_	1.8, 3, 3.3		1.8	5.5	4	V										PG	0.47 µF C	MSP430; lowest I <sub>n</sub>	0.32
TPS715xx	50	415	3.2		2.5, 3, 3.3, 5	V	2.5		4	V											0.47 µF C	Ultra-low I <sub>a</sub>	0.32
TPS770xx	50	35	17		1.2, 1.5, 1.8, 2.5, 2.7, 2.8, 3, 3.3, 5	V	2.7	10	3		V									/EN	4.7 μF T	Low I <sub>a</sub>	0.34
TPS722xx	50	50	80		1.5, 1.6, 1.8	V	1.8	5.5	3		V									EN	0.1 µF C	Low noise & low V <sub>IN</sub>	0.39
TPS760xx	50	120	90		3, 3.2, 3.3, 3.8, 5.0		3.2	16	2		V									EN	2.2 µF T	Bipolar, low cost	0.34
TPS769xx	100	70	18		1.2, 1.5, 1.8, 2.5, 2.7, 2.8, 3, 3.3, 5	V	2.7	10	3		V									/EN	4.7 μF T	Low cost	0.29
REG101	100	60	400		2.5, 2.8, 2.85, 3, 3.3, 5	V	2.6	10	1.5		V		V							EN, BP	No Cap	Low noise	0.88
TPS791xx	100	38	185		1.8, 3.3, 4.7	V	2.7	5.5	2		V									/EN, BP	1μFC	RF low noise, high PSRR	0.38
TPS792xx	100	38	185		2.5, 2.8, 3	V	2.7	5.5	2		V									EN, BP	1 μF C	RF low noise, high PSRR	0.38
TPS761xx	100	170	90		3, 3.2, 3.3, 3.8, 5		3.4	16	2		V									EN	4.7 µF T	Bipolar, low cost	0.35
TPS763xx	150	180	85		1.6, 1.8, 2.5, 2.7, 2.8, 3, 3.3, 3.8, 5	V	2.7	10	3		V									EN	4.7 µF T	Low cost	0.29
TPS764xx	150	300	85		2.5, 2.7, 2.8, 3, 3.3		2.7	10	3		V									EN, BP	4.7 µF T	TPS763xx + low noise	0.29
TPS771xx	150	75	90		1.5, 1.8, 2.7, 2.8, 3.3, 5	V	2.7	10	2				V							/EN, SVS	10 µF T	Low noise	0.56
TPS731xx	150	60	450		1.5, 1.8, 2.5, 3.0, 3.3, 5.0	1	1.8	5.5	2		~		Ť							EN, BP	No Cap	Reverse leakage protection	0.45
SN105125	150	1 V	150		1.2	÷	3	5.25	2		1									EN, PG	1μF C	Low cost	0.29
TPS788xx	150	150	18		2.5, 3.3		2.7	10	3		V									/EN	4.7 µF T	USB inrush control	0.36
TPS721xx	150	150	90		1.5, 1.6, 1.8	V	1.8	5.5	3		V									EN	0.1 μF C	Low noise & low V <sub>IN</sub>	0.30
TL750/1Lxx	150	600	1 mA		5, 10, 12		6	26	4											/EN	10 μF T	60-V load dump	0.45
TPS793xx	200	77	180			V	2.7	5.5	2		~						v			EN, BP	2.2 μF C	RF low noise, high PSRR	0.40
TPS793xx	200	145	172	_	1.8, 2.5, 2.8, 2.85, 3, 3.3, 4.75	4	2.7	5.5	2		V	V								EN, BP	2.2 μF C 2.2 μF C	· · · ·	0.40
		145			1.8, 2.5, 2.8, 3, 3.3							V		~								RF low noise, high PSRR	
TPS732xx	250		450		1.5, 1.8, 2.5, 3, 3.3, 5.0	~	1.8	5.5	2		r			~						EN, BP	No Cap	Reverse leakage protection	0.65
TPS773xx	250	125	90		1.5, 1.6, 1.8, 2.7, 2.8, 3.3, 5	~	2.7	10	2			V								/EN, SVS	10 µF T	Low noise	0.65
TPS779xx	250	250	90		1.8, 2.5, 3	~	2.7	10	2			~								EN, SVS	10 µF T	Low noise	0.65
REG102	250	150	400		2.5, 2.8, 2.85, 3, 3.3, 5	~	2.6	10	1.5		V		V	~						EN, BP	No Cap	Capacitor free, DMOS	1.00
TPS736xx	400	160	450	_	1.5, 1.8, 2.5, 3.0, 3.3	~	1.8	5.5	2		~			~			_			EN, BP	No Cap	Reverse leakage protection	0.80
REG113	400	250	400		2.5, 2.85, 3, 3.3, 5		2.6	10	1.5		V	~								EN, BP	No Cap	Capacitor free, DMOS	1.04
TPS795xx	500	105	265		1.6, 1.8, 2.5, 3, 3.3	V	2.7	5.5	3					~						EN, BP	1 µF C	RF low noise, high PSRR	0.95
TPS775xx	500	169	87		1.5, 1.6, 1.8, 2.5, 3.3	V	2.7	10	2				~		V					/EN, SVS	10 µF T	Fast transient response	0.87
TPS776xx	500	169	87		1.5, 1.8, 2.5, 2.8, 3.3	V	2.7	10	2				~		V		_			/EN, PG	10 µF T	Fast transient response	0.83
REG103	500	115	500		2.5, 2.7, 3, 3.3, 5	V	2.6	15	2				V	V		1			V	EN, PG	No Cap	Capacitor free, DMOS	2.00
TPS777xx	750	260	85		1.5, 1.8, 2.5, 3.3	V	2.7	10	2				V		V					/EN, SVS	10 µF T	Fast transient response	0.96
TPS725xx	1000	170	75		1.5, 1.6, 1.8, 2.5	V	1.8	6	2				V	V		1			V	EN, SVS	No Cap	Low noise; SVS delay 50 ms	1.04
TPS726xx	1000	170	75		1.5, 1.6, 1.8, 2.5	—	1.8	6	2					V		1				EN, SVS	No Cap	Low noise; SVS delay 200 ms	1.04
TPS796xx	1000	200	310		1.8, 2.5, 2.8, 3, 3.3	V	2.7	5.5	2					v		~			V	EN, BP	1 µF C	RF low noise, high PSRR	1.04
TPS767xx	1000	230	85		1.5, 1.8, 2.5, 2.7, 2.8, 3, 3.3, 5	V	2.7	10	2				V		V					/EN, SVS	10 µF T	Fast transient response	1.04
TPS768xx	1000	230	80		1.5, 1.8, 2.5, 2.7, 2.8, 3, 3.3, 5	V	2.7	10	2				V		V					/EN, PG	10 µF T	Fast transient response	1.00
UCCx81-x	1000	500	400		3.3, 5	V	1.8	9	2.5				V							EN	2.2 µF T	Reverse leakage protection	1.80
REG104	1000	230	600		2.5, 2.7, 3, 3.3, 5	V	2.6	15	2					V		V			V	EN	No Cap	Capacitor free, DMOS	2.22
TLV1112	1000	1200	5 mA		1.2	_	2.7	18	2.5					~		1	1				10 µF T	Low cost regulator	0.35
TLV1117	1000	1200	5 mA		1.5, 1.8, 2.5, 2.85, 3.3, 5	1	2.7	18	2.5					~		1	V				10 µF T	Low cost regulator	0.32
TPS786xx	1500	390	310		1.8, 2.5, 2.8, 3, 3.3	V	2.7	5.5	3					V		V			V	EN, BP	1μF C	RF low noise, high PSRR	1.28
TPS751xx	1500	160	75		1.5, 1.8, 2.5, 3.3	V	2.7	5.0	2						V					/EN, PG	47 µF T	Fast transient response	1.52
TPS752xx	2000	210	75		1.5, 1.8, 2.5, 3.3	V	2.7	5.0	2						~					/EN, SVS	47 μF T	Fast transient response	1.71
TPS754xx	2000	210	75		1.5, 1.8, 2.5, 3.3	V	2.7	5.0	2						V					/EN, PG	47 µF T	Fast transient response	1.65
UC382-x	3000	350	6 mA		1.5, 2.1, 2.5	v	1.7	7.5	1						•	~	V		V	,,	100 μF T	Fast LDO with reverse leak.	2.57
UCC383-x	3000	400	400		3.3, 5	v	1.8	9	2.5							1	V		V	/EN	22 µF T	Reverse leakage protection	2.57
TPS758xx	3000	150	110		1.5, 1.8, 2.5, 3.3	v	2.8	5.5	3							~	v		v	EN	47 μF T	Fast transient response	2.57
UC385-x	5000	350	8 mA			v	1.7		3 1							~	V		v	LIN	47 μF T 100 μF T	Fast LDO with reverse leak.	3.00
	5000	350 250			1.5, 2.1, 2.5			7.5 5.5											v	EN			
TPS756xx			110		1.5, 1.8, 2.5, 3.3	~	2.8		3								V		V		47 μF T	Fast transient response	2.83
TPS759xx	7500	400	110		1.5, 1.8, 2.5, 3.3	V	2.8	5.5	3							V	V		V	/EN, PG	47 µF T	Fast transient response	3.04

**Rise/Fall** 

Time

(ns)

25/25

I<sub>0</sub>

Source/Sink

(A)

4.0/4.0

**Reference Accuracy (%)** 

Prop

Delay

(ns)

35

Share Bus

Single Ended

Input

Threshold

TTL/CMOS

V<sub>CC</sub>

Range

(V)

4 to 15

<sup>1</sup>PG = PowerGood, EN = Active High Enable, /EN = Active Low Enable, SVS = Supply Voltage Supervisor <sup>3</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

Output

Туре

TrueDrive

<sup>2</sup>C = Ceramic, T = Tantalum, No Cap = Capacitor Free LDO New devices are listed in red.

Protection

Features

Supply Current (mA)

2.5

Internal

Regulator

No

Price<sup>1</sup>

0.99

Price<sup>1</sup>

0.89

Dead

Time

Control

No

Enable

No

Pin Count

8

Logic

**General Overview** 

**Signal Chain** 

**Timing & Interface** 

Device

Device

UCC37323

UCC29002	4	15	
<sup>1</sup> Suggested resale	price in U.S. dollar	s in quantities of 1,0	00.

V<sub>IN</sub> (max)

Output

Configuration

Inverting

<sup>1</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

LOADSHARE CONTROLLERS

V<sub>IN</sub> (min)

No. of

Outputs

2

## **DUAL-OUTPUT LDOs**

						Output Optio	ns					Features									
Device	I <sub>01</sub> (mA)	I <sub>02</sub> (mA)	V <sub>D01</sub> @ I <sub>01</sub> (mV)	V <sub>D02</sub> @ I <sub>02</sub> (mV)	Ι <sub>q</sub> @ Ι <sub>Ο</sub> (μΑ)	Voltage (V)	Adj.	Accuracy (%)	PWP Package	Min V <sub>0</sub>	Max V <sub>0</sub>	/EN	PG	SVS	Seq	Low Noise	Min V <sub>IN</sub>	Max V <sub>IN</sub>	C <sub>0</sub> 1	Description	Price <sup>2</sup>
TPS707xx	250	150	83	—	95	3.3/2.5, 3.3/1.8, 3.3/1.5, 3.3/1.2	~	2	~	1.2	5	4	4	4	۷	~	2.7	5.5	10 µF T	Dual-output LDO with sequencing	1.91
TPS708xx	250	150	83	—	95	3.3/2.5, 3.3/1.8, 3.3/1.5, 3.3/1.2	~	2	~	1.2	5	•	~	1		~	2.7	5.5	10 µF T	Dual-output LDO with independent enable	1.91
TPS701xx	500	250	170	—	95	3.3/2.5, 3.3/1.8, 3.3/1.5, 3.3/1.2	~	2	~	1.2	5	4	4	~	۷	~	2.7	5.5	10 µF T	Dual-output LDO with sequencing	2.17
TPS702xx	500	250	170	—	95	3.3/2.5, 3.3/1.8, 3.3/1.5, 3.3/1.2	4	2	~	1.2	5	•	4				2.7	5.5	10 µF T	Dual-output LDO with independent enable	2.17
TPS767D3xx	1000	1000	230	—	170	3.3/2.5 3.3/1.8	4	2	~	1.2	5	•		~			2.7	10	10 µF T	Dual-output FAST LDO with integrated SVS	2.17
TPPM0110	1500	300	1000	2500	1000	3.3/1.8		2		1.8	3.3						4.7	5.3	$100 \ \mu F \ T$	Outputs track within 2 V	1.62
TPPM0111	1500	300	1000	2800	1000	3.3/1.5		2		1.5	3.3						4.7	5.3	100 µF T	Outputs track within 2 V	1.60
TPS703xx	2000	1000	160	—	185	3.3/2.5, 3.3/1.8, 3.3/1.5, 3.3/1.2	4	2	~	1.2	5	4	4	4	۷	4	2.7	5.5	22 µF T	Dual-output LDO with sequencing	2.30
TPS704xx	2000	1000	160	—	185	3.3/2.5, 3.3/1.8, 3.3/1.5, 3.3/1.2	4	2	4	1.2	5	4	4	~		~	2.7	5.5	22 µF T	Dual-output LDO with independent enable	2.30

<sup>1</sup>T = Tantalum

<sup>2</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

## **PLUG-IN POWER SOLUTIONS**

Device <sup>1</sup>	Input Bus Voltage (V)	Description	P <sub>OUT</sub> or I <sub>OUT</sub>	lsolated Outputs	V <sub>O</sub> Range (V)	V <sub>0</sub> Adjustable	Price <sup>2</sup>		
Isolated Multiple	Output								
PT4820	48	35-W 48-V Input Triple Low-Voltage Isolated DC/DC Converter	35 W	Yes	1.2 to 5.0	Yes	64.83		
PT4850	48	75-W 48-V Input Triple Low-Voltage Isolated DC/DC Converter	75 W	Yes	1.2 to 3.3	Yes	96.64		
Isolated Single Output									
PT4410	48	100-W 30-A 48-V Input Isolated Programmable DC/DC Converter	100 W	Yes	1.05 to 5.7	5-bit programmable	70.20		
<sup>1</sup> See <b>powerti.com</b> for a complete product offering.									

<sup>2</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

## **HOT SWAP CONTROLLERS (EXTERNAL FET)**

Device	Target Applications	Channels	V <sub>IN</sub> (V)	Enable/ Shutdown	Power Good or UVLO Reporting	Ramp	Automatic Retry/Latch	Average Power Limiting	Price <sup>1</sup>
TPS2390	–48-V Telecom	1	-36 to -80	1H	UVLO	Current	Latch	No	1.15
TPS2391	–48-V Telecom	1	-36 to -80	1H	UVLO	Current	AutoRetry	No	1.15

<sup>1</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

## **DC/DC CONTROLLERS**

		V <sub>IN</sub>	V <sub>0</sub> (max)	V <sub>0</sub> (min)	V <sub>ref</sub> Tol	Driver Current	Output Current	Multiple	Adaptive Voltage			
Devic	e	(V)	(V)	(V)	(%)	(A)	(A) <sup>1</sup>	Outputs	Positioning	Protection <sup>2</sup>	Comments	Price <sup>3</sup>
Performance Processor Power Supply Controllers (Synchronous Rectification)												
TPS4	0000	2.25 to 5.5	4	0.7	1.5	1	15	No	No	OCP, UVLO	300-kHz low input sync buck, source only	0.99
TPS4	0001	2.25 to 5.5	4	0.7	1.5	1	15	No	No	OCP, UVLO	300-kHz low input sync buck, source/sink	0.99
											except SS	
TPS4	0002	2.25 to 5.5	4	0.7	1.5	1	15	No	No	OCP, UVLO	600-kHz low input sync buck, source only	0.99
TPS4	0003	2.25 to 5.5	4	0.7	1.5	1	15	No	No	OCP, UVLO	600-kHz low input sync buck, source/sink	0.99
											except SS	
TPS4	10050	8 to 40	30	0.7	1	1	20	No	No	OCP, UVLO	Wide input range sync buck, source only	1.32
TPS4	10051	8 to 40	30	0.7	1	1	20	No	No	OCP, UVLO	Wide input range sync buck, source/sink	1.32
TPS4	0053	8 to 40	30	0.7	1	1	20	No	No	OCP, UVLO	Wide input range sync buck, source/sink	1.32
											except SS	
TPS4	10060	10 to 55	40	0.7	1	1	10	No	No	OCP, UVLO	Wide input range sync buck, source only	1.32
TPS4	10061	10 to 55	40	0.7	1	1	10	No	No	OCP, UVLO	Wide input range sync buck, source/sink	1.32

<sup>1</sup>Current levels of this magnitude and beyond can be supported. <sup>2</sup>OCP — over-current protection; UVLO — under-voltage lockout <sup>3</sup>Suggested resale price in U.S. dollars in quantities of 1,000.

New devices are listed in red.

New devices are listed in red.

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